

TAS5631DKD2EVM

This user's guide describes the operation of the evaluation module for the TAS5631 Digital Amplifier Power Output Stage using TAS5518 Digital Audio PWM Processor from Texas Instruments. The user's guide also provides measurement data and design information like schematic, BOM, and PCB layout.

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1 Introduction

The TAS5631DKD2EVM PurePath™ HD customer evaluation module demonstrates the integrated circuits TAS5631DKD and TAS5518PAG from Texas Instruments.

The TAS5631DKD is a high-performance, integrated Stereo Feedback Digital Amplifier Power Stage designed to drive 4-Ω speakers at up to 300 W per channel. The device incorporates the TI Equibit™ technology and is designed to be used with TI's Equibit™ modulators. This system only requires a passive demodulation filter to deliver a efficiency, quality audio amplification.

TAS5518PAG is a high performance 32 bit (24 bit input) multi channel PurePath™ Digital Pulse Width Modulator (PWM) based on Equibit™ technology with fully symmetrical AD modulation scheme. The device also has Digital Audio Processing (DAP) that provides 48 bit signal processing, advanced performance and a high level of system integration. The device has interfaces for headphone output and Power Supply Volume Control (PSVC).

This EVM is configurable to 2 BTL channels for stereo evaluation or 1 PBTL (parallel BTL) channel for subwoofer evaluation.

This EVM, together with a TI input-USB board 2, is a complete stereo digital audio amplifier system which includes digital input (S/PDIF), analog inputs, interface to PC and DAP features like digital volume control, input and output mixers, automute, tone controls, loudness, EQ filters and dynamic range compression (DRC). There are configuration options for power stage failure protection.

Table 1. TAS5631DKD2EVM Specification

Key Parameters	Values
Output Stage Supply Voltage	25V – 50 V
Number of Channels	2 x BTL or 1 x PBTL
Load Impedance BTL	4-8 Ω
Load Impedance PBTL	2-3 Ω
Output power BTL	330 W / 4 Ω 10% THD or 180 W / 8 Ω / 10% THD
Output power PBTL	600 W / 2 Ω / 10% THD
DNR	>105 dB
PWM Processor	TAS5518PAG
Output Stage	TAS5631DKD

This document covers EVM specifications, audio performance and power efficiency measurements graphs, and design documentation that includes schematics, parts list, layout, and mechanical design.

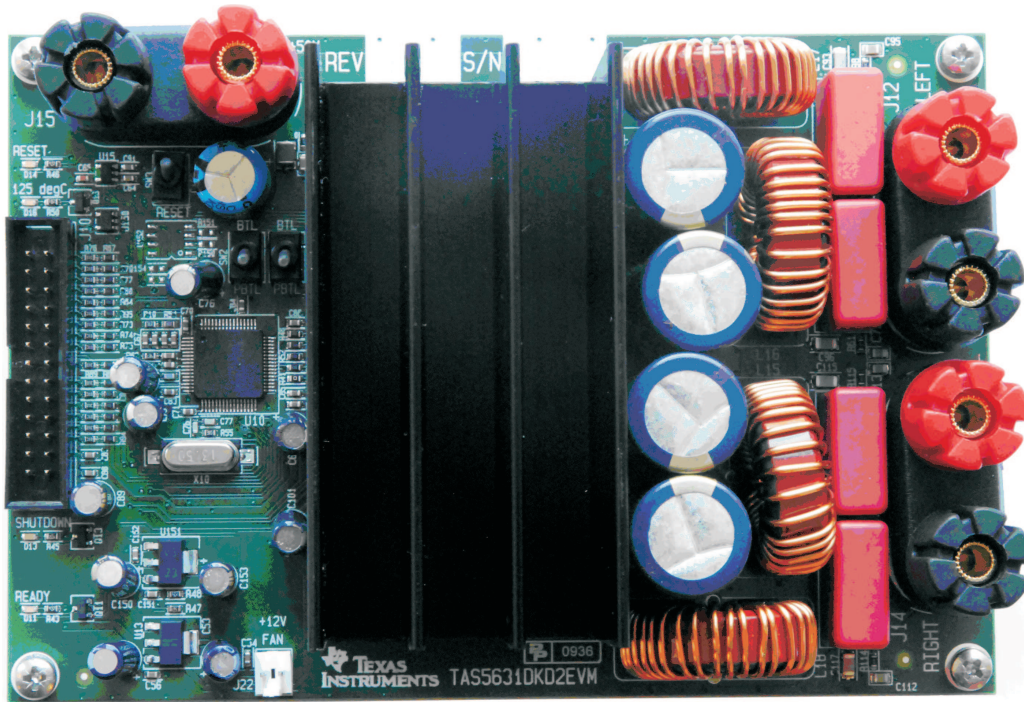


Figure 1. TAS5631DKD2EVM – Top View

Gerber (layout) files are available at: www.ti.com.

The EVM is delivered with cables and Input-USB board 2 to connect to an input source, and be controlled from a PC.

1.1 TAS5631DKD2EVM Features

- Stereo PurePath Digital™ evaluation module.
- Self-contained protection system (short circuit and thermal).
- Standard I²S and I²C™ / Control connector for TI input board
- Double-sided plated-through PCB layout.

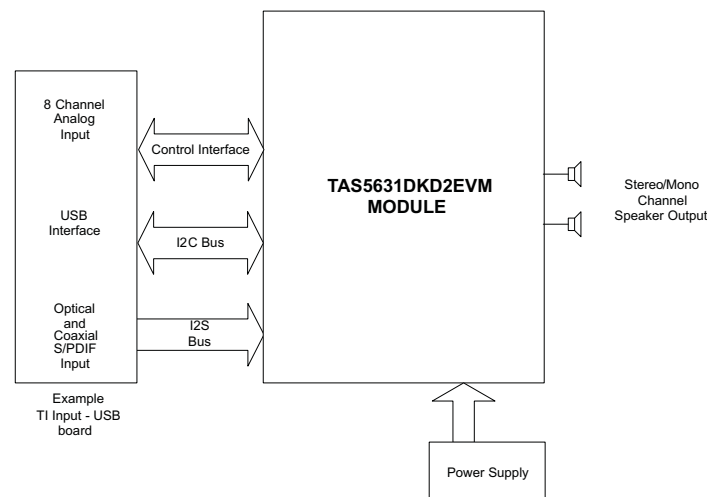


Figure 2. Integrated PurePath Digital™ Amplifier System

1.2 PCB Key map

Physical structure for the TAS5631DKD2EVM is illustrated in [Figure 3](#).

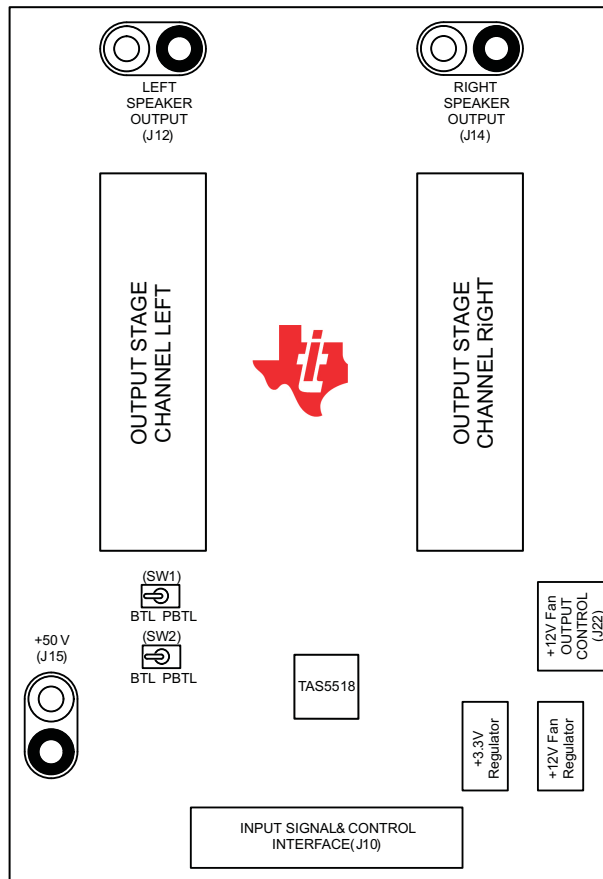


Figure 3. Physical Structure for the TAS5631DKD2EVM (Approximate Layout)

2 Quick Setup Guide

This section describes the TAS5631DKD2EVM board in regards to power supplies and system interfaces. The section provides information regarding handling and unpacking, absolute operating conditions, and a description of the factory default switch and jumper configuration.

This section also provides a step-by-step guide to configuring the TAS5631DKD2EVM for device evaluation.

2.1 Electrostatic Discharge Warning

Many of the components on the TAS5631DKD2EVM are susceptible to damage by electrostatic discharge (ESD). Customers are advised to observe proper ESD handling precautions when unpacking and handling the EVM, including the use of a grounded wrist strap at an approved ESD workstation.

CAUTION

Failure to observe ESD handling procedures can result in damage to EVM components.

2.2 Unpacking the EVM

Upon opening the TAS5631DKD2EVM package, check to make sure that the following items are included:

- 1 pc. TAS5631DKD2EVM board using one TAS5518PAG and one TAS5631DKD.
- 1 pc. TI Input-USB board 2 for interfacing TAS5631DKD2EVM with SPDIF/analog sources and PC for control.
- 1 pc. Signal and Control Interface IDC cable for connection to an I²S front-end like the attached TI Input-USB board 2.
- 1 pc. Cable for connecting Input-USB board 2 to a USB port on a PC for TAS5518 control by software.
- 1 pc. AC to DC External 15 V Power supply (System supply).
- 4 pcs. AC Input Clips for External 15 V Power Supply (US, Europe, UK and Australia).
- 1 pc. PurePath™ CD-ROM.

If any of these items are missing, contact the nearest Texas Instruments Product Information Center to inquire about a replacement.

Connect the Input-micro board to the TAS5631DKD2EVM using the delivered IDC cable.

2.3 Power Supply Setup

To power up the EVM, two power supplies are needed. One for system power, logic and gate-drive, and one for output stage supply. H-bridge Power supply is connected to the EVM using banana cables. System Power Supply is supplied from the enclosed External 15 V wall plug adapter.

Table 2. Table 2. Recommended Supply Voltages

Description	Voltage Range	Current Requirements	Cable
Output stage power supply	25 – 50 V	16 A	J15 (marked +50V)

CAUTION

Applying voltages above the specifications given in [Table 2](#) can cause permanent damage to the hardware.

NOTE: The length of power supply cable must be minimized. Increasing length of PSU cable is equal to increasing the distortion for the amplifier at high output levels and low frequencies.

2.4 Speaker Connection

CAUTION

Both positive and negative speaker outputs are floating and cannot be connected to ground (e.g. through an oscilloscope).

2.5 Output configuration BTL and PBTL

When changing mode e.g. from BTL to PBTL, make sure that RESET is activated before changing the state of mode switches SW1 and SW2. Switch SW1 and SW2 has to be synchronized in state BTL or PBTL.

In PBTL mode the load has to be connected according to [Figure 4](#):

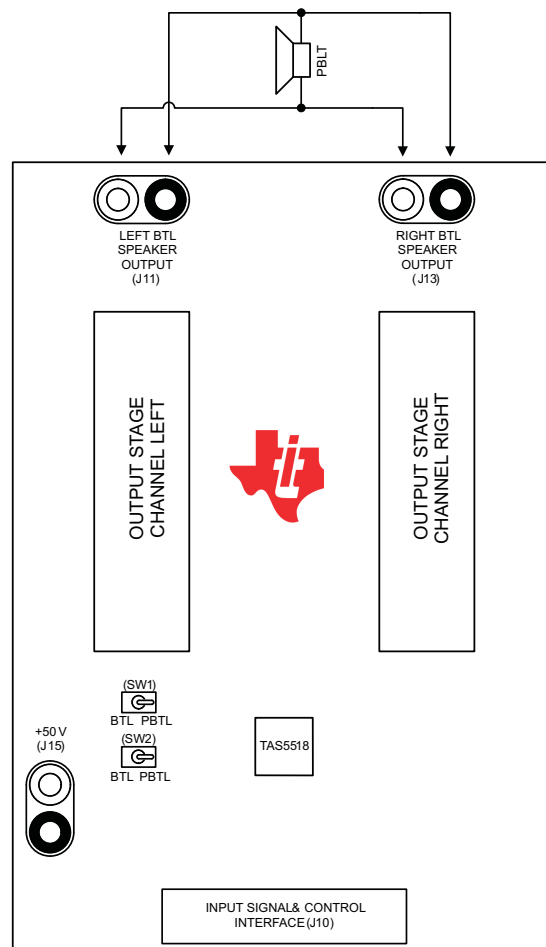


Figure 4. PBT Mode Configuration

2.6 GUI Software Installation

The TAS5518 GUI provides control of all registers in the TAS5518. To install the GUI, run the setup file from the PurePath™ CD-rom.

After installation turn on power supplies and connect the USB cable to the Input-USB board 2.

Start the GUI program from windows menu. Start up of the GUI will take a few seconds.



Figure 5. TAS5518 GUI Window

From the files menu load the configuration file:

- TAS5631DKD2EVM Configuration (1.00).cfg

The file is located in the EVM folder on the TI website. This file contains all settings for a default setup of the EVM.

For access to the file, it is recommended that the user copy the files into the directory where the GUI is installed. The default is C:\Program Files\Texas Instruments Inc\TAS5518\

For more advanced use of the GUI, see the GUI User's Guide and data manual for TAS5518.

3 Protection

This section describes the short-circuit protection and fault reporting circuitry of the TAS5631 device.

3.1 Short Circuit Protection and Fault Reporting Circuitry

The TAS5631 is a self-protecting device that provides fault reporting (including high-temperature protection and short circuit protection). TAS5631 is configured in back-end auto-recovery mode, and resets automatically after all errors (M1, M2 and M3 is set low), see the data sheet ([sles221](#)) for further explanation. The device will re-start itself after an error occasion, and report through the SD error signal.

3.2 Fault Reporting

The \overline{OTW} and \overline{SD} outputs from TAS5631 indicate fault conditions. see the TAS5631 data sheet for a description of these pins.

Table 3. TAS5631 Warning/Error Signal Decoding

SD	OTW1	OTW2	Device Condition
0	0	0	High temperature error and/or high current error
0	0	1	Under voltage lockout or high current error. 100°C temperature warning
0	1	1	Under voltage lockout or high current error
1	0	0	125°C temperature warning
1	0	1	100°C temperature warning
1	1	1	Normal operation, no errors/warnings

The shutdown signals together with the temperature warning signal, give the chip state information as described in Table 3. Device fault reporting outputs are open-drain outputs.

4 TAS5631DKD2EVM Performance

Table 4. General Test Conditions

General Test Conditions ⁽¹⁾	Value	Notes
Output Stage Supply Voltage	50 V	Laboratory Power Supply (EA-PS 7065-10A)
Load Impedance BTL	4-8 Ohm	
Load Impedance PBTL	2 Ohm	
Input Signal	1kHz Sine	
Sampling Frequency	48 kHz	
Gain setting in TAS5518	0 dB	
Measurement Filter	AES17 and AUX0025	
TI Input Board	Input-USB 2	Rev 1
EVM configuration file	Ver 1.00	TAS5631DKD2EVM Configuration (1.00).cfg

⁽¹⁾ These test conditions are used for all tests, unless otherwise specified.

Table 5. TAS5518 Register Settings

Register ⁽¹⁾	Value	Notes
System Control Register 2	0x04	0x60 PWM Automute Detection Disabled
Master Volume Register	0xD9	00 00 00 48 Master Volume set to 0 dB

⁽¹⁾ These test conditions are used for all tests, unless otherwise specified.

Table 6. Electrical Data

General Test Conditions	Value	Notes
Output Power, BTL, 4Ω	180 W	1 kHz, unclipped (0dBFS), T _A = 25°C
Output Power, BTL, 4Ω	330 W	1 kHz, 10% THD+N, T _A = 25°C
Output Power, BTL, 8Ω	100 W	1 kHz, unclipped (0dBFS), T _A = 25°C
Output Power, BTL, 8Ω	180 W	1 kHz, 10% THD+N, T _A = 25°C
Output Power, PBTL, 2Ω	330 W	1 kHz, unclipped (0 dBFS), T _A = 25°C
Output Power, PBTL, 2Ω	600 W	1 kHz, 10% THD+N, T _A = 25°C, TC < 50°C
Maximum Peak Current, BTL	>16 A	1 kHz burst, 1 Ohm, ROC = 24 kΩ
Maximum Peak Current, PBTL	>28 A	1 kHz burst, 1 Ohm, ROC = 24 kΩ
Output Stage Efficiency	>94 %	2 x channels, 8 Ω
Damping Factor BTL	>16	1 kHz, relative to 4 Ω load
Damping Factor PBTL	>18	1 kHz, relative to 2 Ω load
H-Bridge Supply Current	<65 mA	1 kHz, -60dBFS signal
Idle Power Consumption	3.3 W	H-Bridge supply, -60dBFS input signal

Table 7. Audio Performance

Audio Performance		Value	Notes
THD+N, BTL, 4Ω	1 W	<0.02 %	1 kHz
THD+N, BTL, 4Ω	10 W	<0.02 %	1 kHz
THD+N, BTL, 4Ω	50 W	<0.02 %	1 kHz
THD+N, BTL, 4Ω	200 W	<0.5 %	1 kHz
THD+N, BTL, 8Ω	1 W	<0.02 %	1 kHz
THD+N, BTL, 8Ω	10 W	<0.02 %	1 kHz
THD+N, BTL, 8Ω	50 W	<0.02 %	1 kHz
THD+N, BTL, 8Ω	100 W	<0.5 %	1 kHz
THD+N, PBTL, 2Ω	1 W	<0.02 %	1 kHz
THD+N, PBTL, 2Ω	10 W	<0.02 %	1 kHz
THD+N, PBTL, 2Ω	100 W	<0.03 %	1 kHz
THD+N, PBTL, 2Ω	200 W	<0.05 %	1 kHz
THD+N, PBTL, 2Ω	400 W	<0.5 %	1 kHz
Dynamic Range		>105 dB	Ref: rated power, A-weighted, AES17 filter, 4 ch avg
Noise Voltage		<190 μVrms	A-weighted, AES17 filter
Click/Pop, DC step BTL		18 mV	Mute/Unmute, No signal, 6 Ohm
Click/Pop, DC step PBT		18 mV	Mute/Unmute, No signal, 4 Ohm
Channel Separation		>80 dB	1 kHz
Frequency Response		+0.5 / -1 dB	100 W / 8 Ω

Table 8. Thermal Specification

Thermal Specification ⁽¹⁾	T _{HEATSINK} ⁽¹⁾	Notes
Idle, All Channels Switching	28°C	1 kHz, 15 min, -60dBFS signal, T _A = 25°C
2x40 W, 4Ω (1/8 power)	42°C	1 kHz, 1 hour, T _A = 25°C
2x200 W, 4Ω	62°C	1 kHz, 5 min, T _A = 25°C

⁽¹⁾ Measured on surface of heat sink.

Table 9. Physical Specifications

Physical Specifications ⁽¹⁾		Notes
PCB Dimensions	94 x 140 x 55	Width x Length x Height (mm)
Total Weight	380 gr.	Components + PCB + Heat-sink + Mechanics

⁽¹⁾ All electrical and audio specifications are typical values.

4.1 THD+N vs. Power

Gain: +2.5dB set in TAS5518

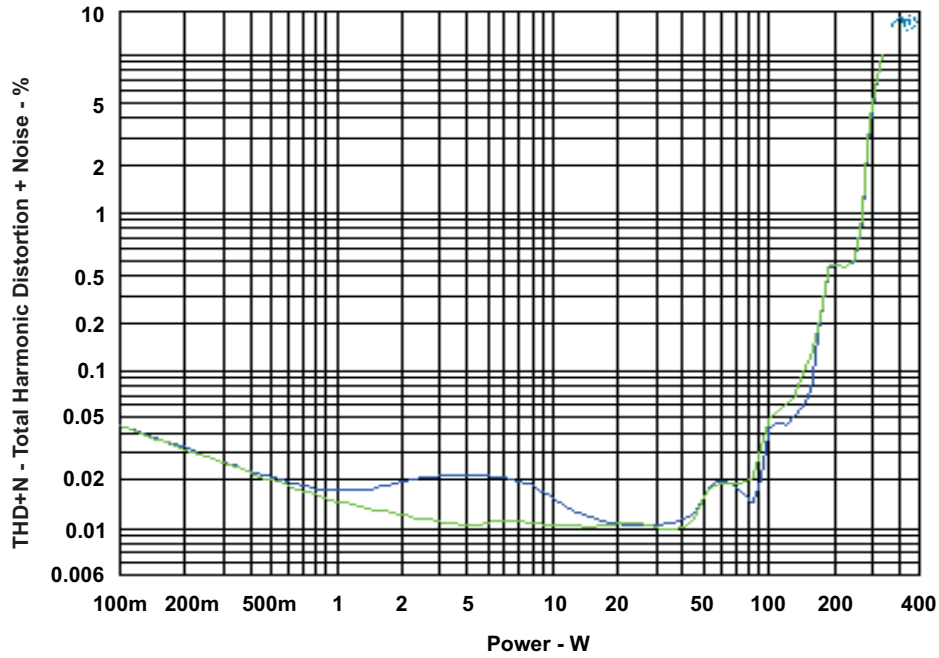


Figure 6. THD+N vs. Power (BTL – 4 Ω)

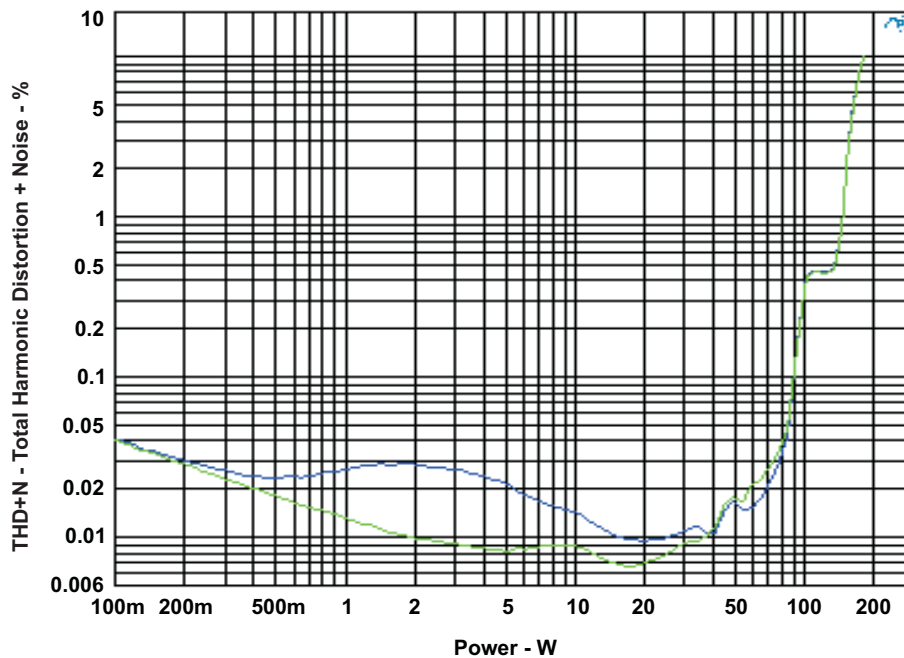


Figure 7. THD+N vs. Power (BTL – 8 Ω)

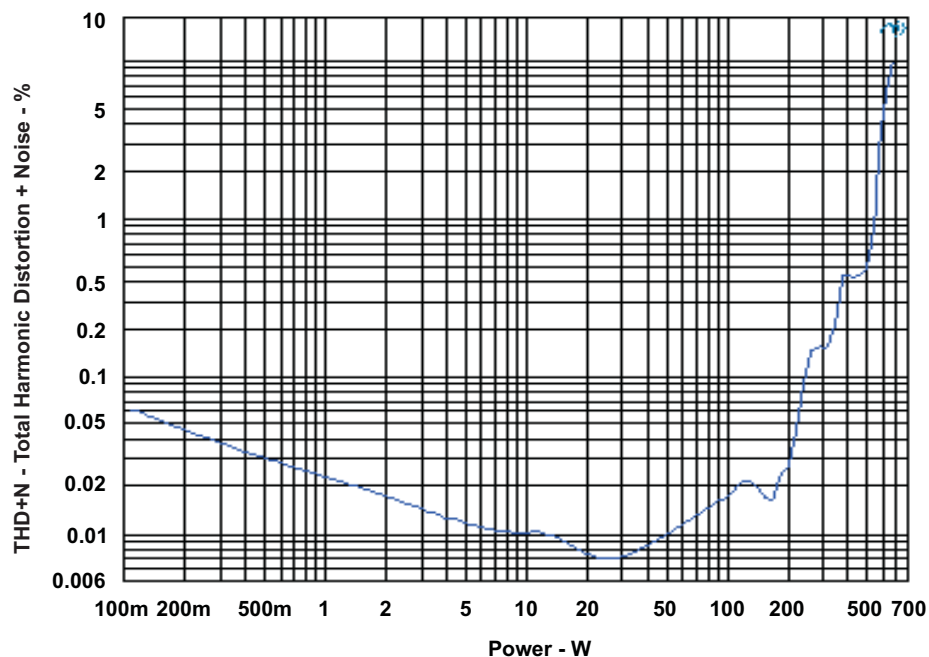


Figure 8. THD+N vs. Power (PBTL – 2 Ω)

4.2 THD+N vs. Frequency

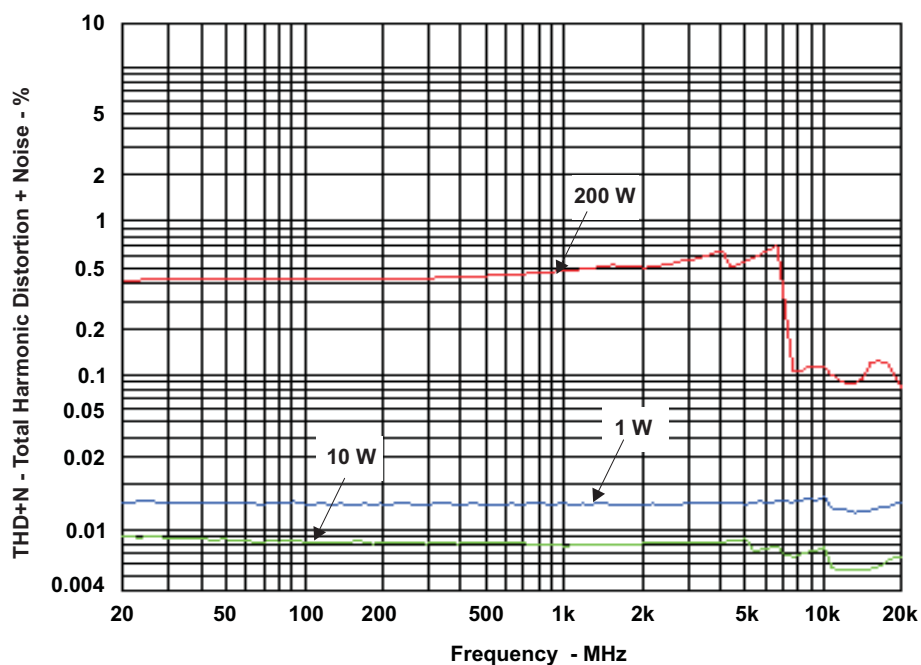


Figure 9. THD+N vs. Frequency (BTL – 4 Ω)

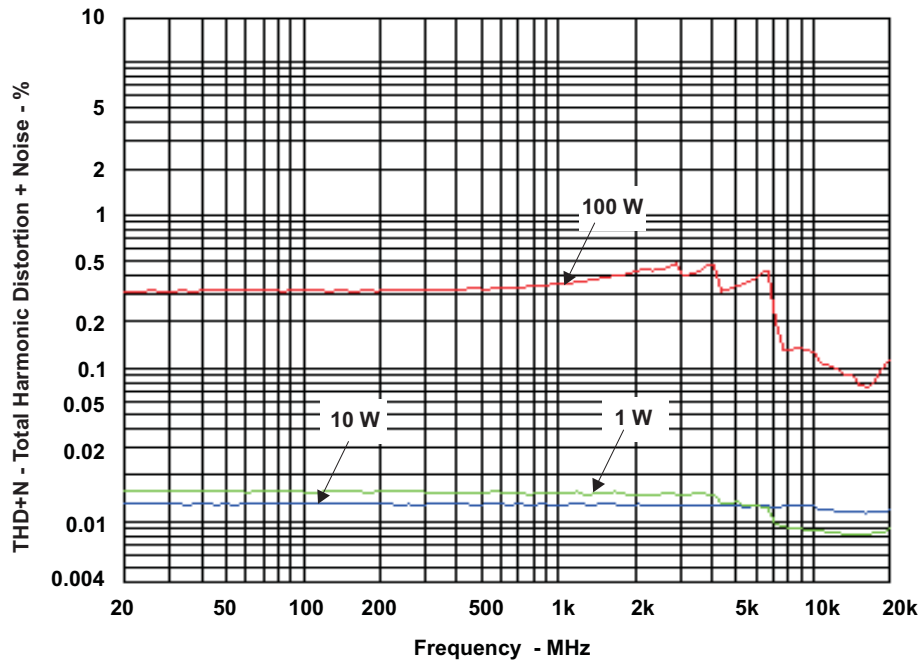


Figure 10. THD+N vs. Frequency (BTL – 8 Ω)

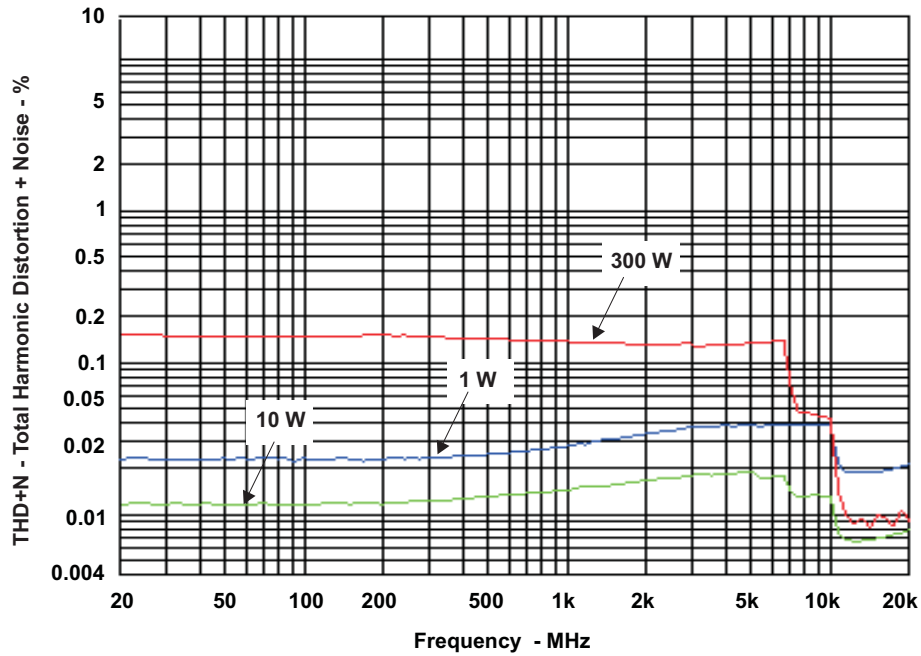


Figure 11. THD+N vs. Frequency (PBTL – 2 Ω)

4.3 FFT Spectrum

Reference voltage is 32.5Vrms. FFT size 16k.

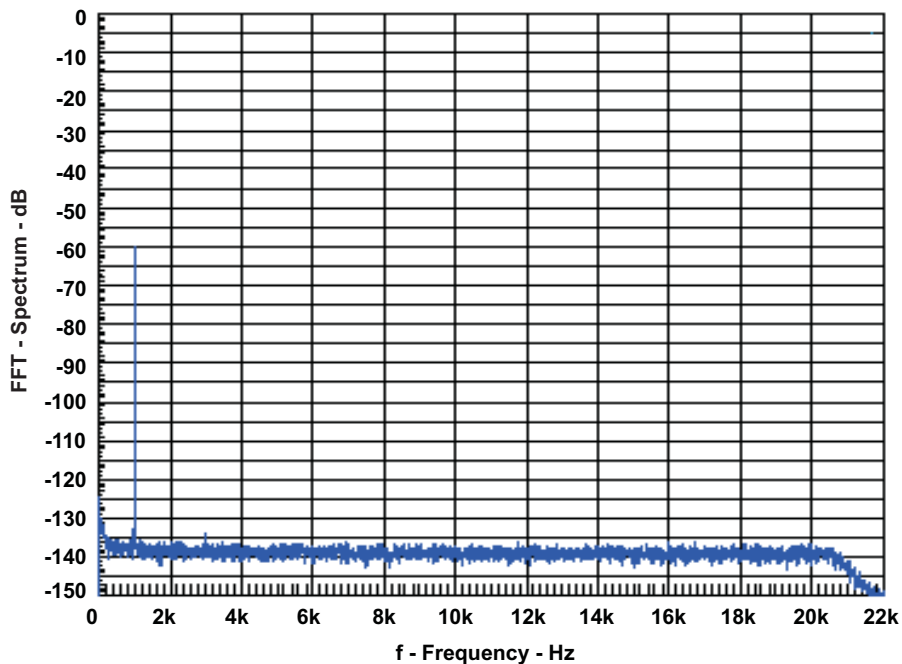


Figure 12. FFT Spectrum with -60 dBFS Tone (BTL)

Reference voltage is 24.8Vrms. FFT size 16k.

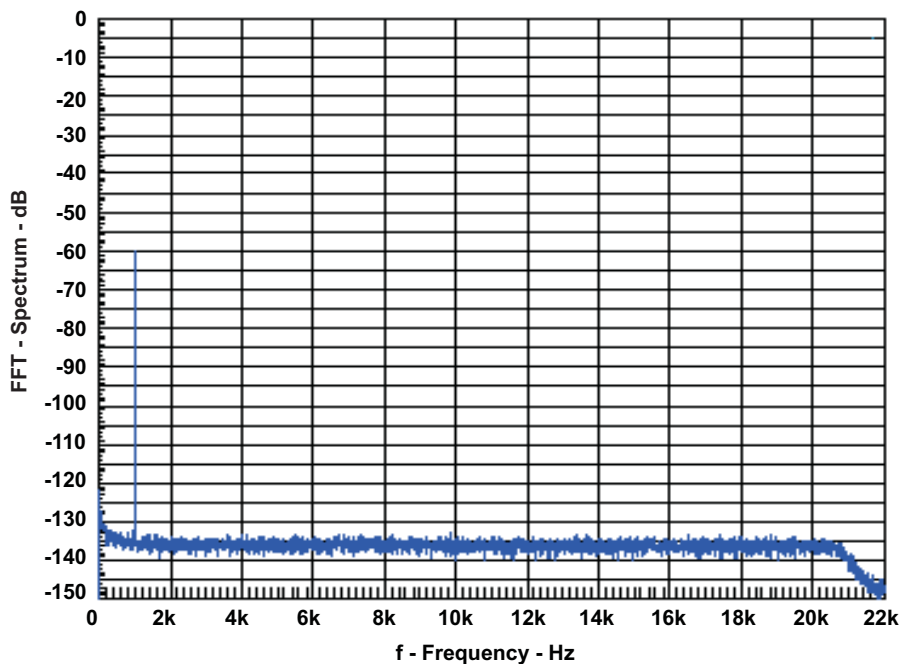


Figure 13. FFT Spectrum with -60 dBFS Tone (PBTl)

4.4 Idle Noise FFT Spectrum

Automute disabled – Register x04h set to x60h. Reference voltage is 32.5V. FFT size 16k.

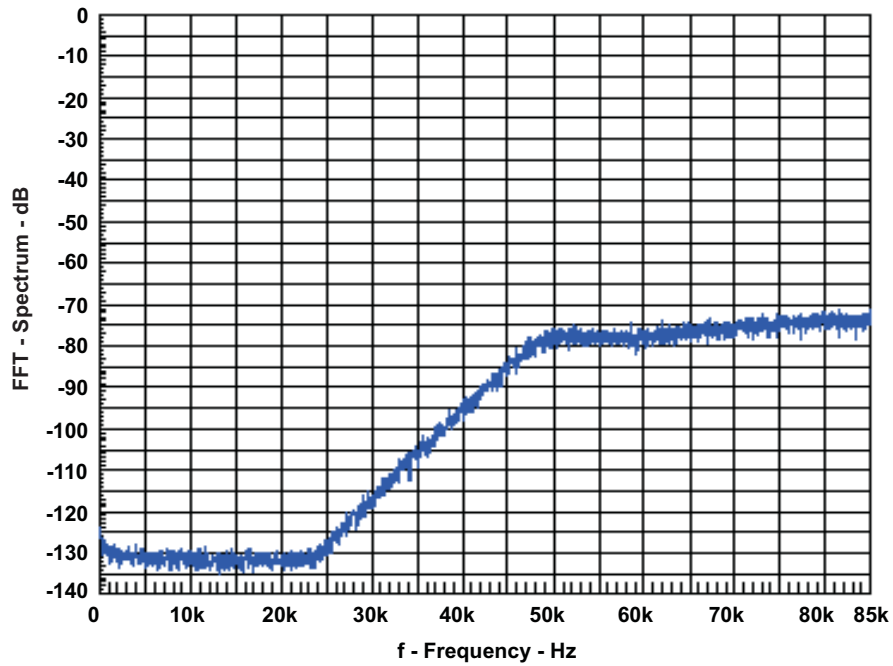


Figure 14. Idle Noise FFT Spectrum (BTL)

Automute disabled – Register x04h set to x60h. Reference voltage is 24.8V. FFT size 16k.

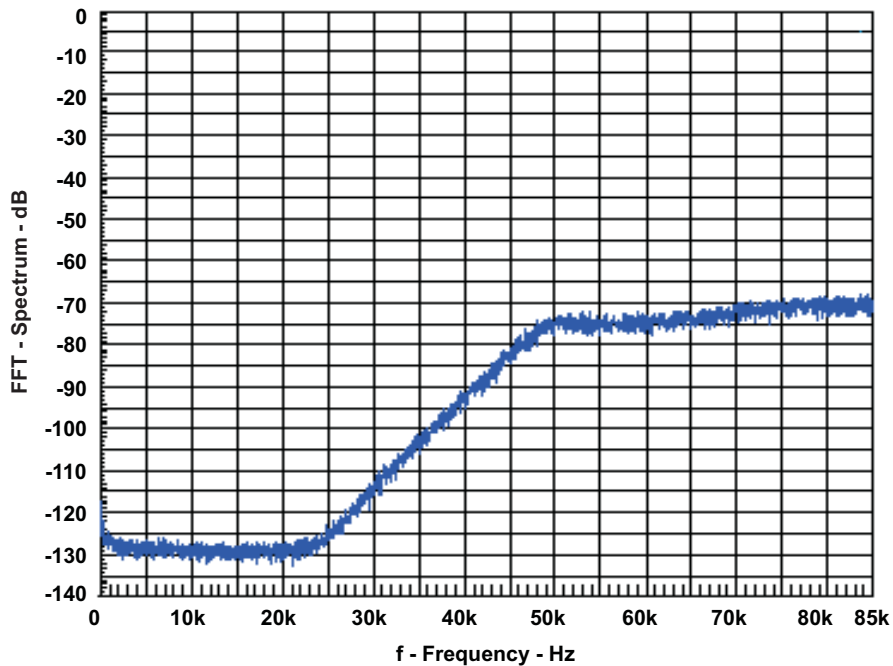


Figure 15. Idle Noise FFT Spectrum (PBTL)

4.5 Channel Separation

Channel 2 input signal is 100 W, channel 1 muted.

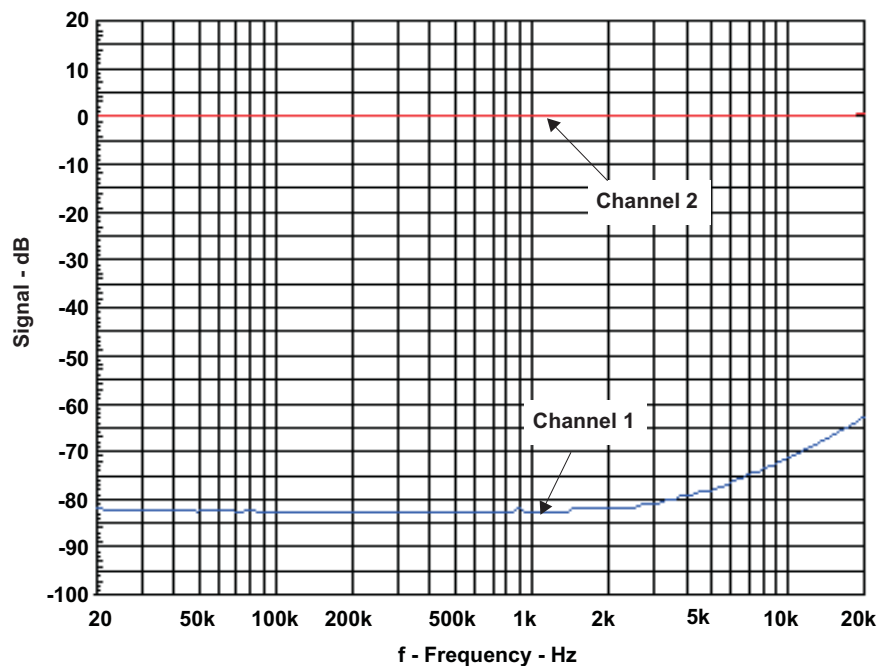


Figure 16. Channel Separation

4.6 Frequency Response

Measurement bandwidth filter 80kHz.

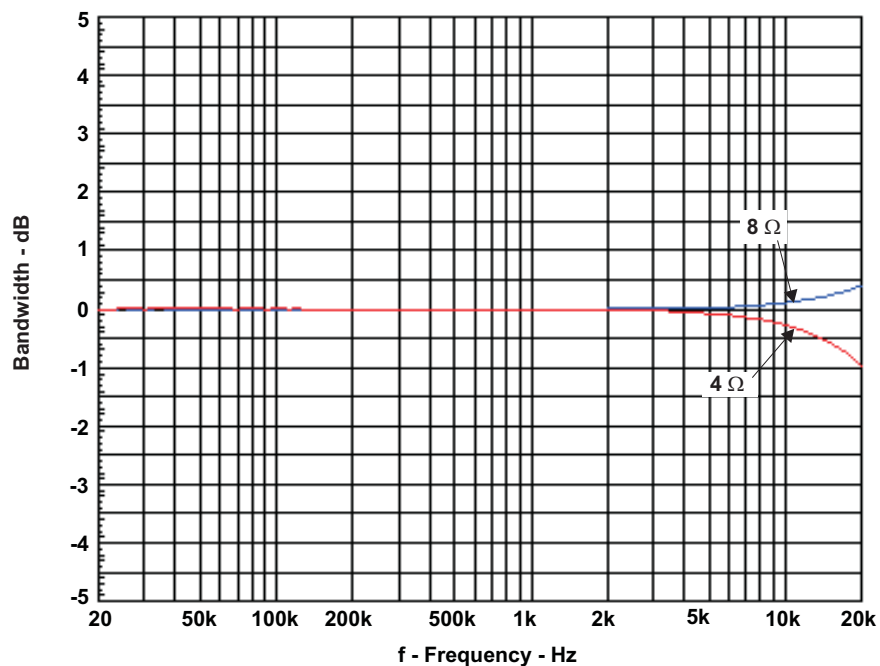


Figure 17. Frequency Response (BTL)

Measurement bandwidth filter 80kHz.

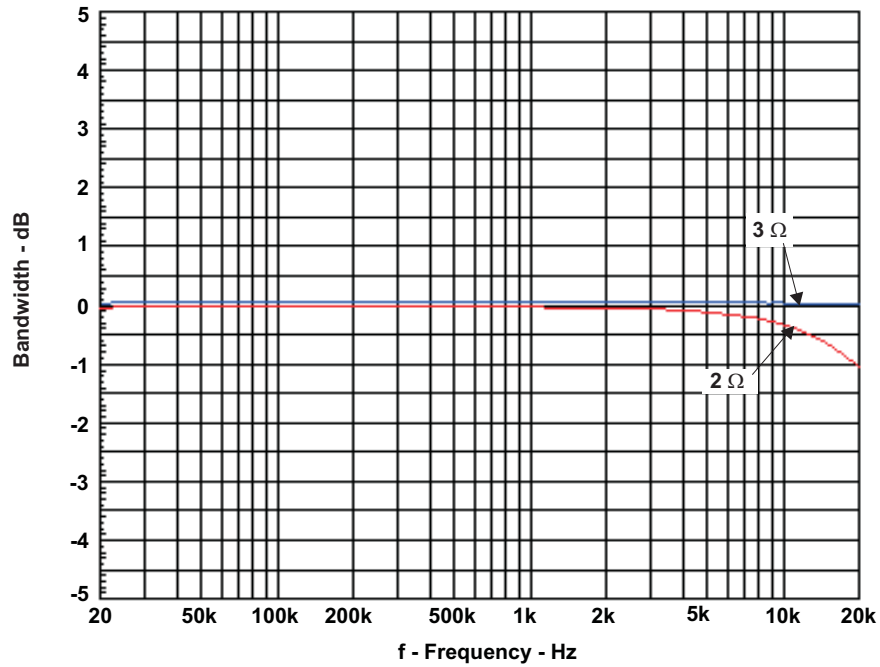


Figure 18. Frequency Response (PBTl)

4.7 High Current Protection

Input 1kHz bursted signal, Load 1Ω.

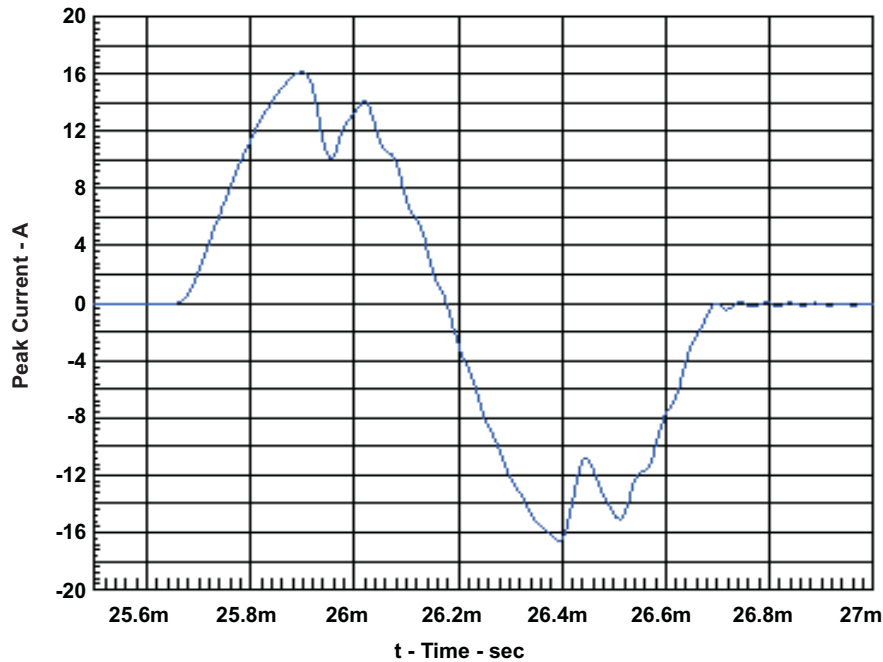


Figure 19. High Current Protection (BTL)

Input 1kHz bursted signal, Load 1Ω.

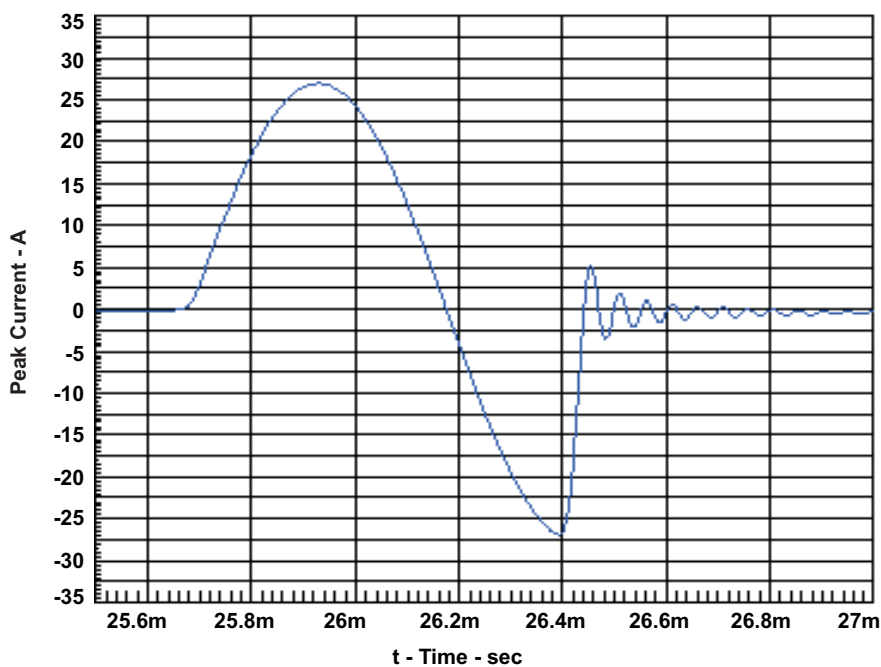


Figure 20. High Current Protection (PBT)

4.8 Pop/Click

No input signal applied. The measurement results are presented in time domain. Test with automute disabled – Register x04h set to x60h. No input signal applied. Load 4Ω.

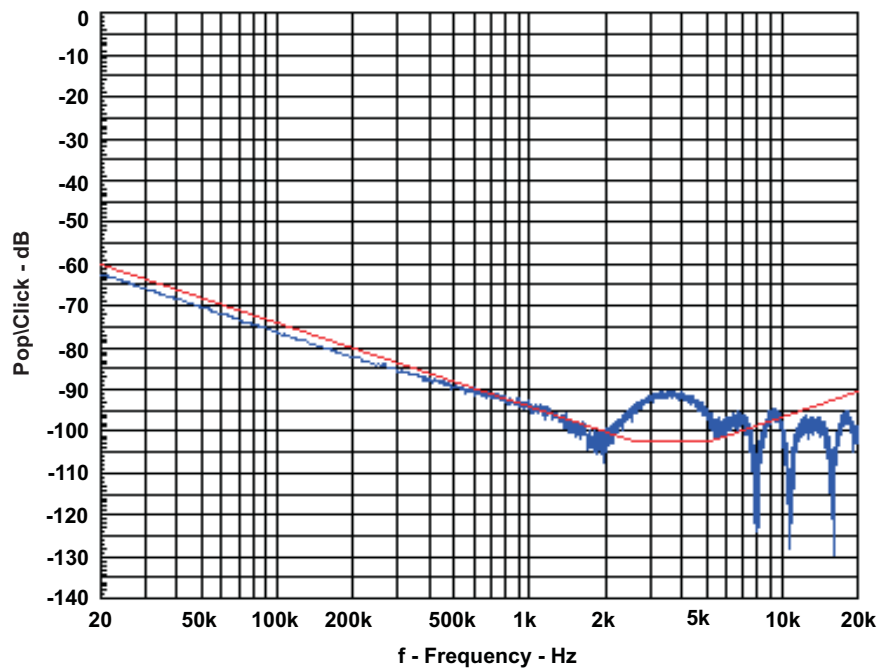


Figure 21. Pop/Click (BTL)

No input signal applied. The measurement results are presented in time domain. Test with automute disabled – Register x04h set to x60h. No input signal applied. Load 2 Ω.

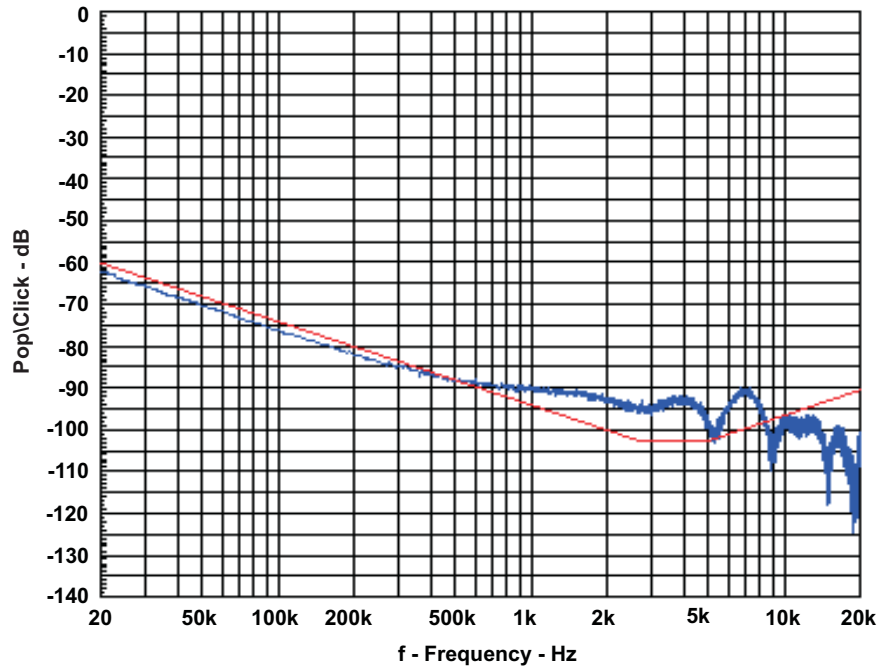


Figure 22. Pop/Click (PBTL)

4.9 Output Stage Efficiency

Efficiency is tested with 2 channels loaded 8Ω.

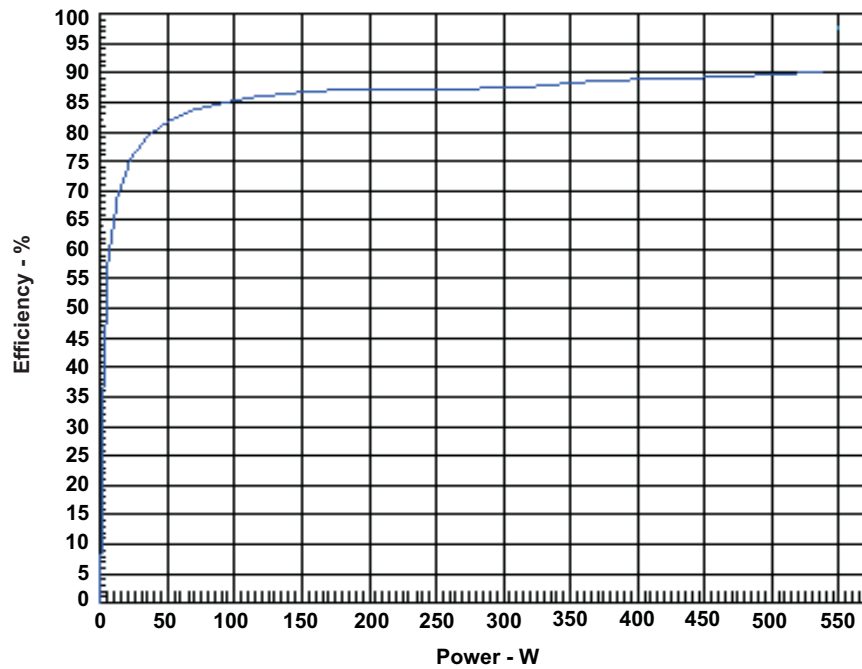


Figure 23. Output Stage Efficiency

5 Related Documentation from Texas Instruments

The following table contains a list of data manuals that have detailed descriptions of the integrated circuits used in the design of the TAS5631DKD2EVM. The data manuals can be obtained at the URL <http://www.ti.com>.

Table 10. Related Documentation from Texas Instruments

Part Number	Literature Number
TAS5518	SLES115
TAS5631	SLES221
TLV271	SLOS351
TPS3825-33	SLVS165
TLV1117-33C	SLVS561

5.1 Additional Documentation

1. PC Configuration Tool for TAS5518 (TAS5518 GUI ver. 4.0 or later)
2. System Design Considerations for True Digital Audio Power Amplifiers ([SLAA117](#))
3. Digital Audio Measurements ([SLAA114](#))
4. PSRR for PurePath Digital Audio Amplifiers ([SLEA049](#))
5. Power Rating in Audio Amplifier ([SLEA047](#))
6. PurePath Digital AM Interference Avoidance ([SLEA040](#))
7. Click & Pop Measurements Technique ([SLEA044](#))
8. Power Supply Recommendations for DVD-Receivers ([SLEA027](#))
9. Implementation of Power Supply Volume Control ([SLEA038](#))

Appendix A Design Documents

This appendix comprises design documents pertaining to the TAS5631DKD2EVM evaluation module. The documents are presented in the following order.

- Schematic (5 pages)
- Parts List (2 pages)
- PCB Specification (1 page)
- PCB Layers (6 pages)
- Heat-Sink Drawing (1 page)



Design Name: **TAS5631DKD2EVM**
 Type: Mass Market EVM
 File Name: A853-SCH-001.DSN
 Version: 2.00
 Date: 17 Aug. 2009
 Design Engineer: Jonas L. Holm (jlh@ti.com) - Jonas Svendsen (jsv@ti.com)
 Audio Configuration: PurePath Premire Pro Digital Amplifier Design
 1 x TAS5631DKD, 1 x TAS5518

Interfaces: J10: 26 pin IDC Header
 for I2S Audio, Control, I2C, +5V and +12V
 J12, J14: Banana binding posts for speaker connection.
 J15: Banana binding post for H-Bridge Supply
 J22: 2 pins 2.54 mm Header for Supply & control of optional external Fan

Setup: 4-8 Ohm (BTL) Speaker Loads
 +50 V H-Bridge Supply Voltage

Performance: 2 x 300 W / 4 Ohm (BTL) 10% THD+N
 > 104 dB Dynamic Range

Page
 1/5: Front Page and Schematic Disclaimer
 2/5: Frontend overview
 3/5: TAS5631 Amplifier
 4/5: Power Supply
 5/5: Mechanics

NOTE1

SCHEMATIC DISCLAIMER

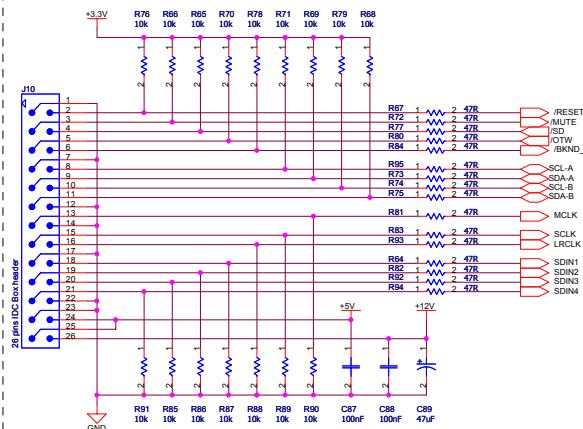
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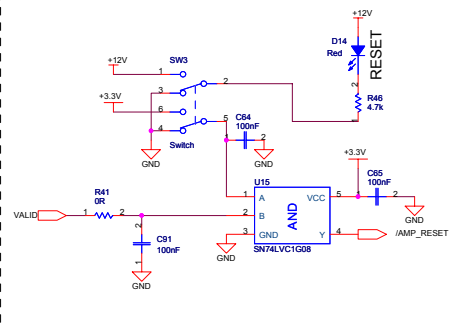
Schematic Disclaimer Preliminary

Parts List 1.00	
TEXAS INSTRUMENTS AUDIO/IMAGING GROUP Home Audio Amplifiers ALL RIGHTS RESERVED TEXAS INSTRUMENTS INCORPORATED	
Project: TAS5616/31DKD2EVM	Rev: 2.00
Page Title: Disclaimer	Size: A3
File Name: A853-SCH-001.DSN	Engineer: Jonas L. Holm
Date: Monday, August 24, 2009	Page: 1 of 5

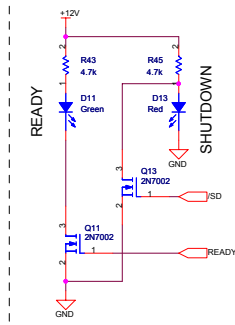
Input and Output Interface: Control, I2C, +5V, +12V and for I2S Audio



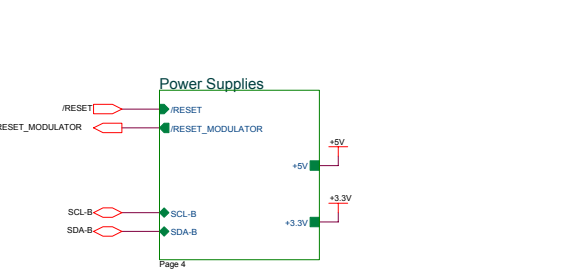
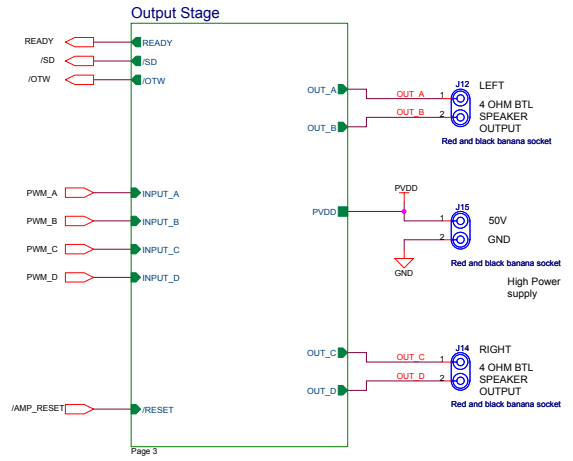
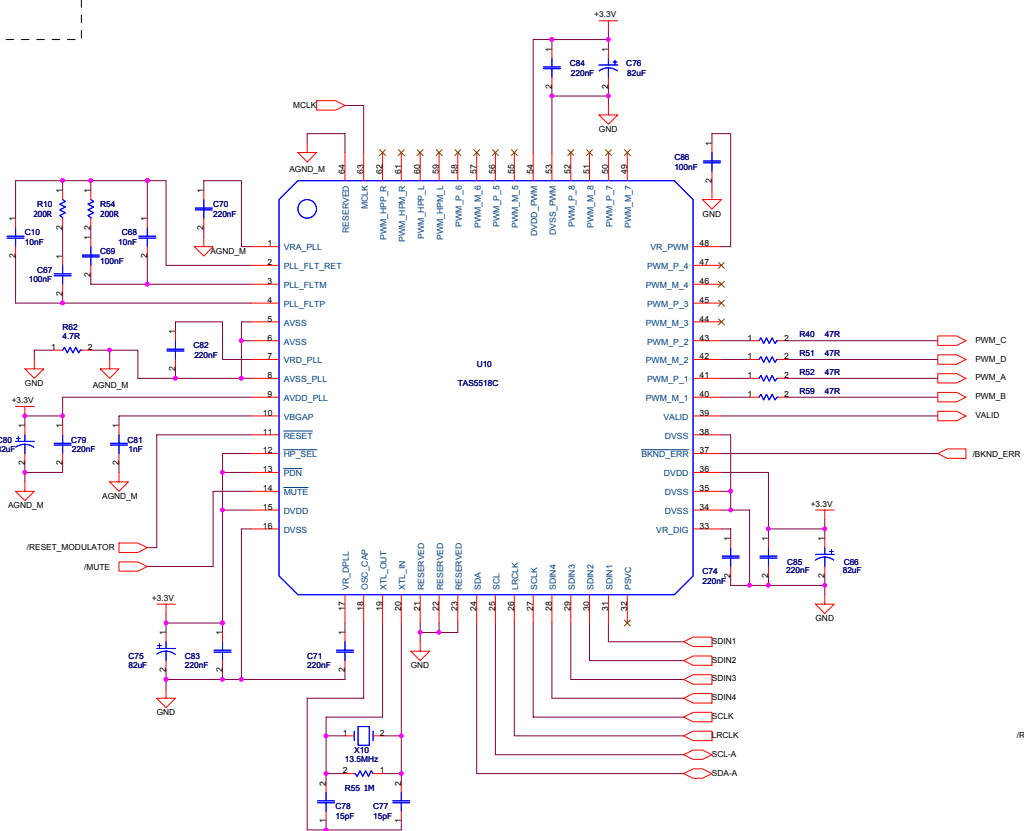
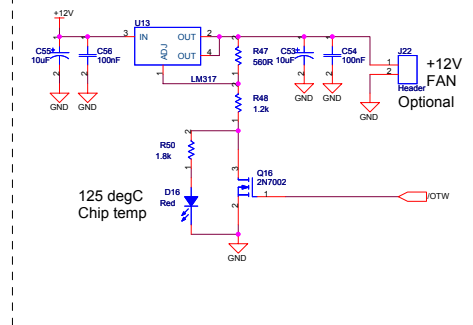
ON/OFF CONTROL

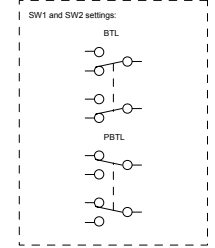
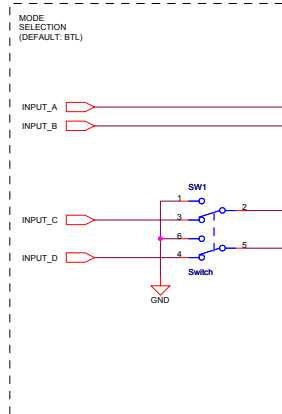
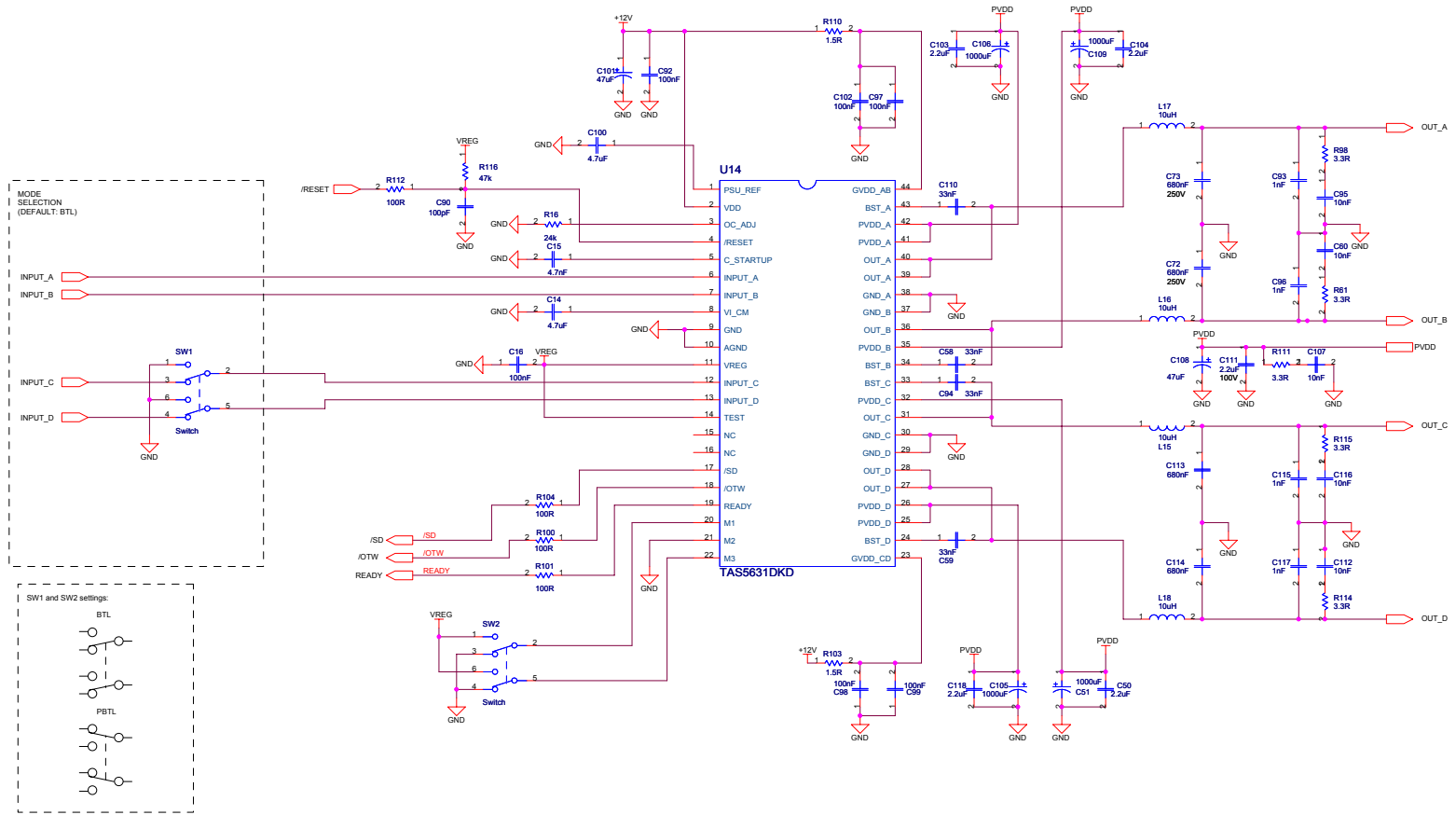


TAS5618 STATUS MONITOR

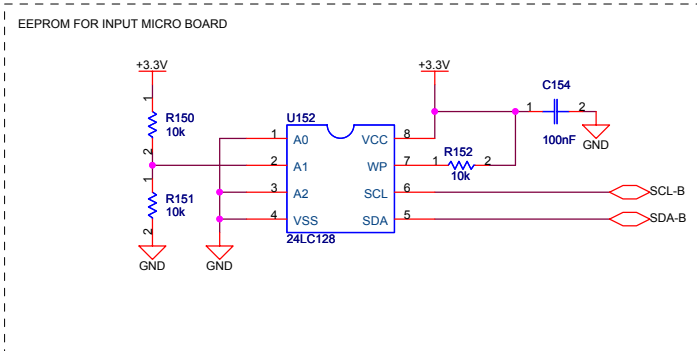
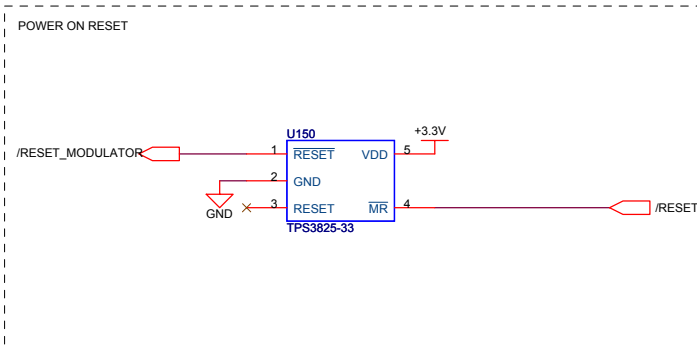
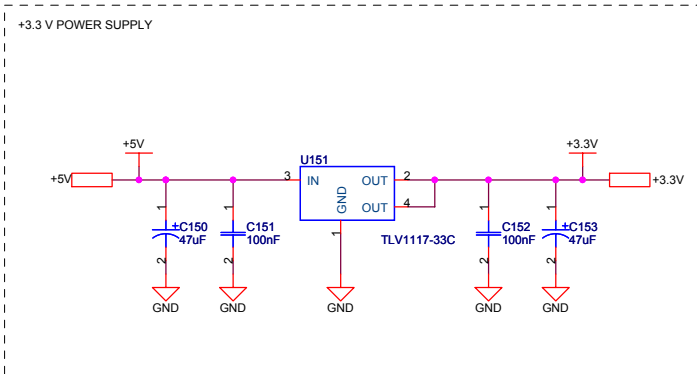


2 SPEED FAN CONTROL & TEMPERATURE INDICATOR

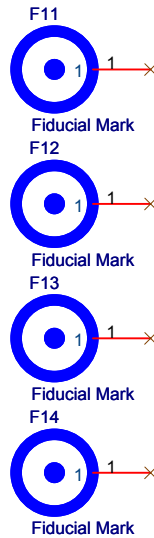
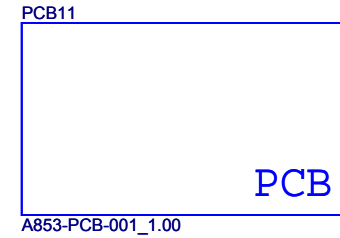
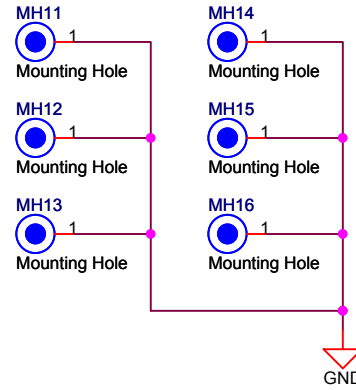
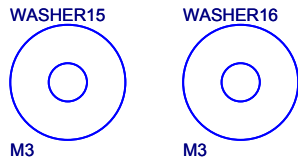
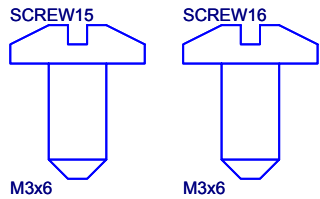
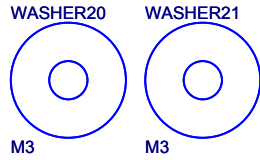
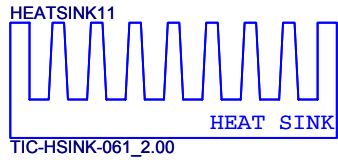
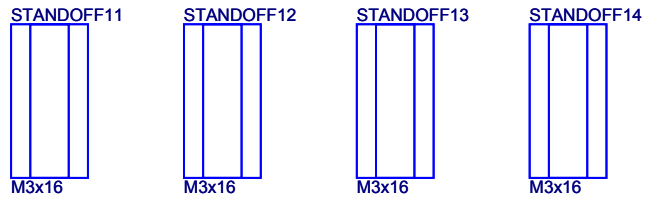
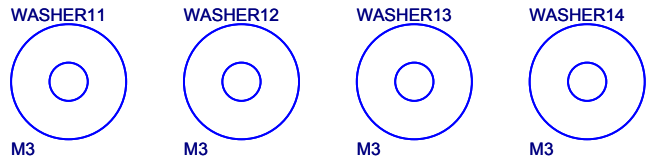
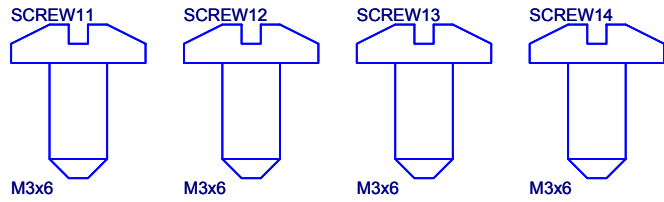




POWER SUPPLIES



MECHANICS



Parts List 1.00



AUDIO/IMAGING GROUP
Home Audio Amplifiers
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Project: TAS5616/31DKD2EVM		Rev: 2.00
Page Title: Mechanics		Size: A4
File Name: A853-SCH-001.DSN	Engineer: Jonas L. Holm	
Date: Monday, August 24, 2009	Page: 5 of 5	

Qty	Part Reference	Description	Manufacture	First Mfr P/N
1	R41	0R / 5% / 0603 Thick Film Resistor	Yageo	RC0603JR-070RL
4	R100 R101 R104 R112	100R / 100mW / 5% / 0603 Thick Film Resistor	Yageo	RC0603JR-07100RL
16	R65 R66 R68 R69 R70 R71 R76 R78 R79 R85 R86 R87 R88 R89 R90 R91	10k / 100mW / 5% / 0603 Thick Film Resistor	Yageo	RC0603JR-0710KL
1	R55	1M / 100mW / 5% / 0603 Thick Film Resistor	Yageo	RC0603JR-071ML
1	R48	1.2k / 100mW / 5% / 0603 Thick Film Resistor	Yageo	RC0603JR-071K2L
2	R103 R110	1.5R / 100mW / 5% / 0603 Thick Film Resistor	Yageo	RC0603JR-071R5L
1	R50	1.8k / 100mW / 5% / 0603 Thick Film Resistor	Yageo	RC0603JR-071K8L
2	R10 R54	200R / 100mW / 5% / 0603 Thick Film Resistor	Yageo	RC0603JR-07200RL
1	R16	24k / 100mW / 1% / 0603 Thick Film Resistor	Yageo	RC0603FR-0724KL
5	R61 R98 R111 R114 R115	3.3R / 100mW / 5% / 0603 Thick Film Resistor	Yageo	RC0603JR-073R3L
3	R43 R45 R46	4.7k / 100mW / 5% / 0603 Thick Film Resistor	Yageo	RC0603JR-074K7L
1	R116	47k / 100mW / 5% / 0603 Thick Film Resistor	Yageo	RC0603JR-0747KL
1	R62	4.7R / 100mW / 5% / 0603 Thick Film Resistor	Yageo	RC0603JR-074R7L
20	R40 R51 R52 R59 R64 R67 R72 R73 R74 R75 R77 R80 R81 R82 R83 R84 R92 R93 R94 R95	47R / 100mW / 5% / 0603 Thick Film Resistor	Yageo	RC0603JR-0747RL
1	R47	560R / 100mW / 5% / 0603 Thick Film Resistor	Yageo	RC0603JR-07560RL
5	C60 C95 C107 C112 C116	Ceramic 10nF / 100V / 20% X7R 0805 Capacitor	BC Components	0805B103M101NT
4	C93 C96 C115 C117	Ceramic 1nF / 100V / 10% NP0 1206 Capacitor	BC Components	1206N102K101NT
5	C50 C103 C104 C111 C118	Ceramic 2.2uF / 100V / 20% X7R 1210 Capacitor	Murata	GRM32ER72A225KA35L
2	C10 C68	Ceramic 10nF / 50V / 20% X7R 0603 Capacitor	Vishay	VJ0603Y103MXA
18	C16 C54 C56 C64 C65 C67 C69 C86 C87 C88 C91 C92 C97 C98 C99 C102 C151 C152	Ceramic 100nF / 16V / 20% X7R 0603 Capacitor	Vishay	VJ0603Y104MXJ
8	C70 C71 C74 C79 C82 C83 C84 C85	Ceramic 220nF / 16V / 20% X7R 0603 Capacitor	BC Components	VJ0603Y224MXJ
4	C58 C59 C94 C110	Ceramic 33nF / 25V / 20% X7R 0603 Capacitor	BC Components	0603B333M250NT
1	C15	Ceramic 4.7nF / 50V / 20% X7R 0603 Capacitor	BC Components	0603B472M500NT
2	C14 C100	Ceramic 4.7uF / 6.3V / 20% X5R 0603 Capacitor	Panasonic	ECJ-1V50J475M
1	C90	Ceramic 100pF / 50V / 10% NP0 0603 Capacitor	BC Components	0603N101K500NT
1	C81	Ceramic 1nF / 50V / 10% NP0 0603 Capacitor	BC Components	0603N102K500NT
2	C77 C78	Ceramic 15pF / 50V / 10% NP0 0603 Capacitor	BC Components	0603N150K500NT
4	C72 C73 C113 C114	Metal Film 680nF / 250V / 20% Polypropylene 15mm (W:8mm L:18mm) Capacitor	Wima	MKP 4 0.68uF/20%/250Vdc PCM15
2	C53 C55	Electrolytic 10uF / 16V / 20% Aluminium 2mm ø5mm M Series - General Purpose Capacitor	Panasonic	ECA1CM100
4	C51 C105 C106 C109	Electrolytic 1000uF / 63V / 20% Aluminium 7.5mm ø16mm FC Series - Low Impedance Capacitor	Panasonic	EEUFC1J102
1	C108	Electrolytic 47uF / 63V / 20% Aluminium 5mm ø10mm Capacitor	BC Components	2222 136 68479
4	C89 C101 C150 C153	Electrolytic 47uF / 16V / 20% Aluminium 2mm ø5mm FC Series - Low Impedance Capacitor	Panasonic	EEUFC1C470
4	C66 C75 C76 C80	Electrolytic 82uF / 16V / 20% Aluminium 2mm ø5mm FC Series - Low Impedance Capacitor	Panasonic	EEUFC1C820
4	L15 L16 L17 L18	10uH / Ferrite Inductor	Toko	C3B-A0336



3	D13 D14 D16	Light Emitting Red Red LED (0603)	Toshiba	TLSU1008
1	D11	Light Emitting Green Green LED (0603)	Toshiba	TLGU1008
3	Q11 Q13 Q16	0.115A / 60V N-ch Power 2N7002 Mosfet (SOT-23)	Fairchild	2N7002
1	U10	TAS5518C / 8 ch PWM processor (AD, DAP, 192kHz, PWM-VOL) (TQFP64)	Texas Instruments	TAS5518CPAG
1	U14	TAS5631DKD / 300 W STEREO FEEDBACK DIGITAL AMPLIFIER (PSOP3-44)	Texas Instruments	TAS5631DKD
1	U15	SN74LVC1G08 / Single AND gate, LVC (SOT23-5)	Texas Instruments	SN74LVC1G08DBVR
1	U150	TPS3825-33 / 3.3V Supply Voltage Supervisor (SOP5-DBV)	Texas Instruments	TPS3825-33DBVT
1	U13	LM317 / 0.5A Positive Adjustable Regulator (DCY)	Texas Instruments	LM317MDCY
1	U151	TLV1117-33C / 3.3V/800mA Positive Voltage Regulator (SOT4-DCY)	Texas Instruments	TLV1117-33CDCYR
6	SCREW11 SCREW12 SCREW13 SCREW14 SCREW15 SCREW16	M3x6 Pan Head, Pozidriv, A2 Screw	Bossard	BN 81882 M3x6
2	WASHER20 WASHER21 WASHER11 WASHER12 WASHER13 WASHER14 WASHER15 WASHER16	M3 White Nylon (o/d:9.0 i/d:3.2 t:0.8) Washer	Bossard	BN1075 M3
6	STANDOFF11 STANDOFF12 STANDOFF13 STANDOFF14	M3 Stainless Steel Spring Washer	Bossard	BN 760 M3
4	STANDOFF11 STANDOFF12 STANDOFF13 STANDOFF14	M3x16 nickel plated brass Stand-off	Bossard	BN 3320 M3x16
1	J22	2 pins / 1 row / 2.54mm Pitch Vertical Male Friction lock Pin header Header	Molex	22-27-2021
1	J10	26 pins / 2 rows / 2.54mm Pitch Vertical Male Low profile IDC 26 pins IDC Box header	Molex	87834-2611
3	J12 J14 J15	2 pins / Vertical Female Banana Red and black banana socket	Cliff	TPP-3CT
1	X10	13.5MHz 13.5MHz SMD Crystal (HCM49)	Citizen	HCM49-13.500MABJT
3	SW1 SW2 SW3	Switch DPDT PCB Mount Switch	NKK-Nikkai	G-22-AP
1	PCB11	A853-PCB-001_2.00 / TAS5631DKD2EVM Printed Circuit Board (ver. 2.00)	Printline	A853-PCB-001(2.00)
1	HEATSINK11	TIC-HSINK-061_2.00 / Heatsink for 1 DKD44 package, length 78 mm	Phonotech	TIC-HSINK-061(2.00)

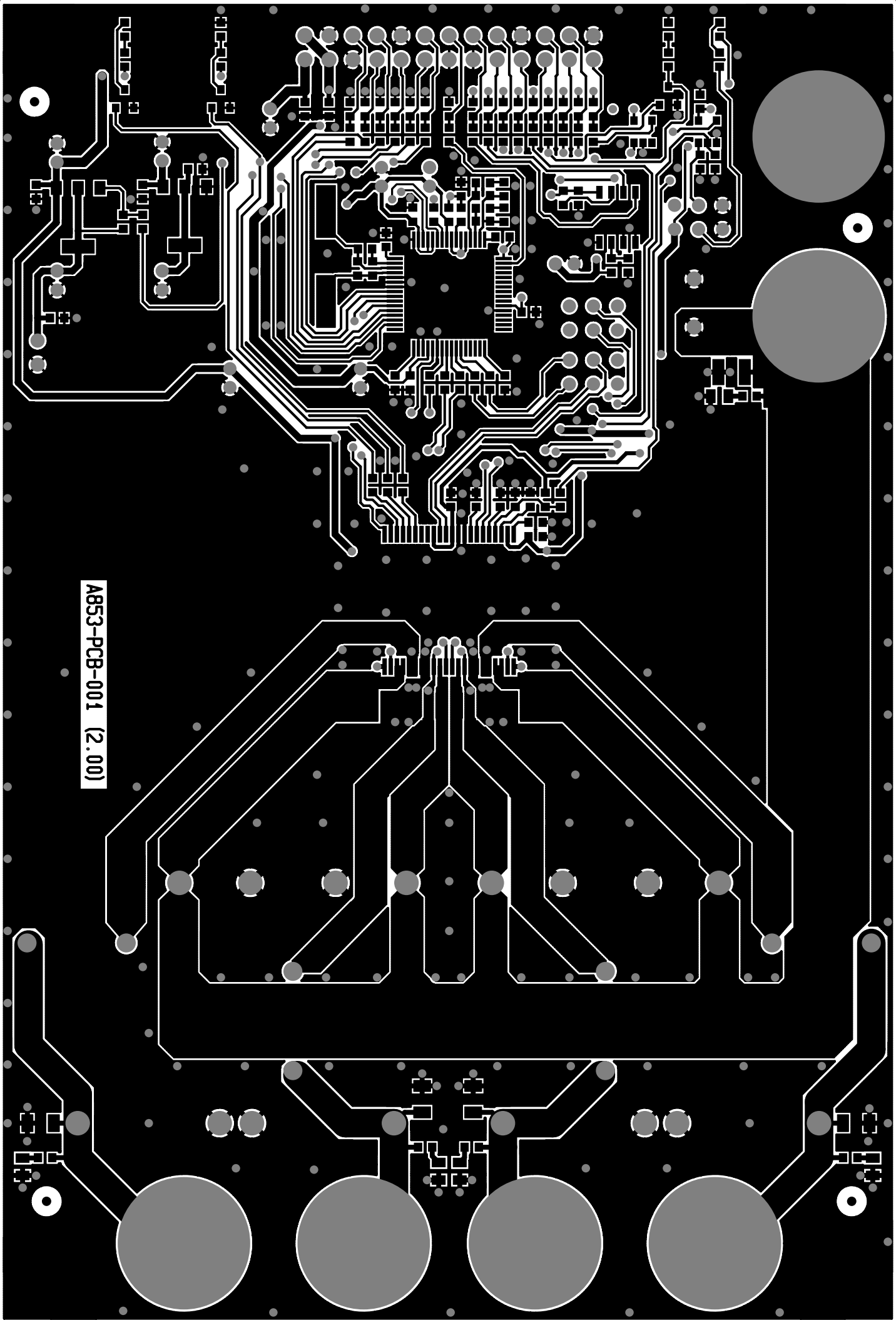
TAS5631DKD2EVM

PCB SPECIFICATION

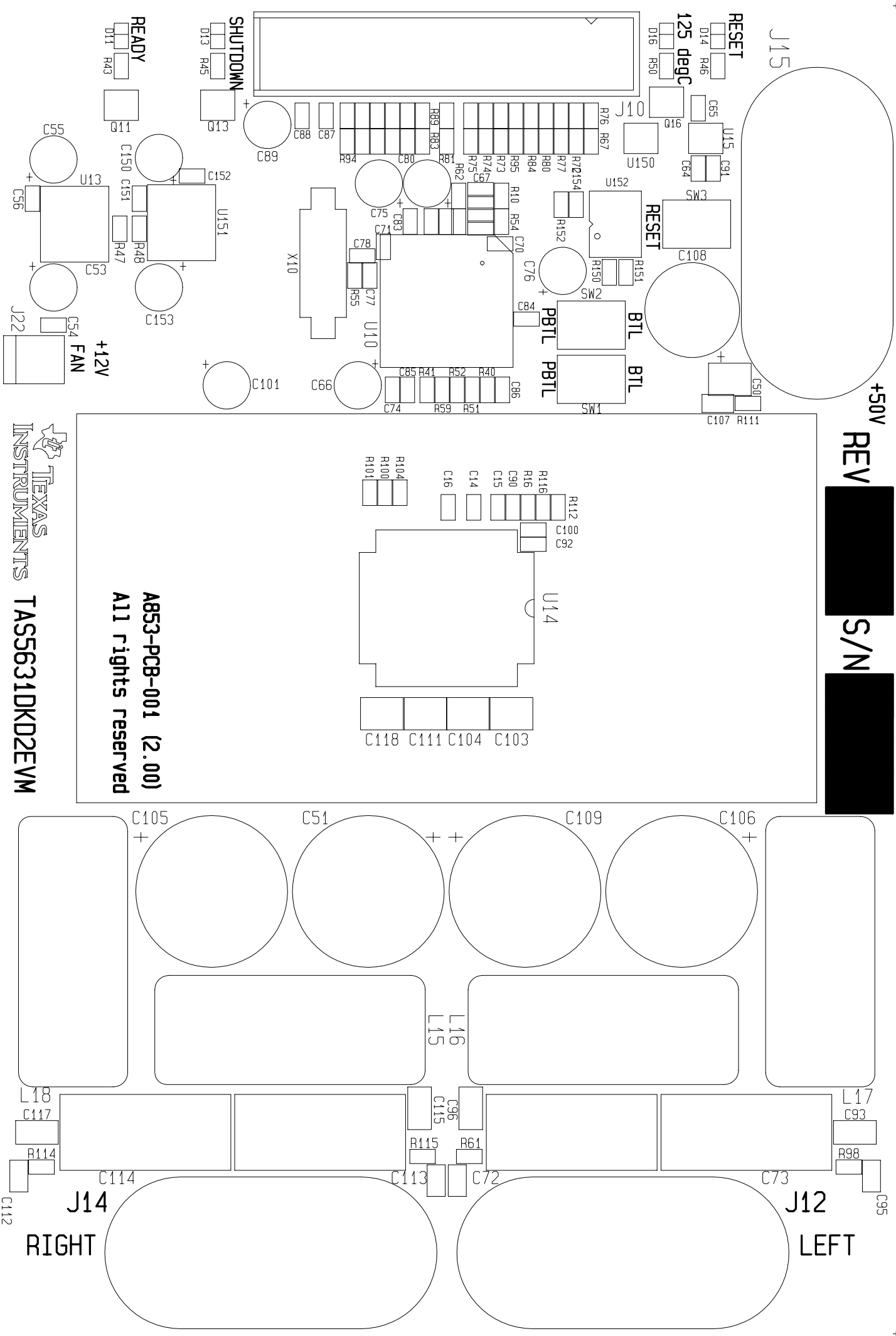
Version 2.00

BOARD IDENTIFICATION:	A853-PCB-001(2.00)
BOARD TYPE:	DOUBLE-SIDED PLATED-THROUGH BOARD
LAMINATE TYPE:	FR4
LAMINATE THICKNESS:	1.6mm
TOP LAYER COPPER THICKNESS:	70 μ m (INCL. PLATING EXTERIOR LAYER)
BOTTOM LAYER COPPER THICKNESS:	70 μ m (INCL. PLATING EXTERIOR LAYER)
COPPER PLATING OF HOLES:	>25 μ m
MINIMUM HOLE DIAMETER	0.3 mm
SILKSCREEN COMPONENT SIDE:	WHITE - REMOVE SILKSCREEN FROM SOLDER AREA & PRE-TINNED AREAS
SILKSCREEN SOLDER SIDE:	None
SOLDER MASK COMPONENT SIDE:	GREEN
SOLDER MASK SOLDER SIDE:	GREEN
PROTECTIVE COATING:	SOLDER COATING AND CHEMICAL SILVER ON FREE COPPER
ELECTRICAL TEST:	PCB MUST BE ELECTRICAL TESTED
MANUFACTURED TO:	PERFAG 2E (www.perfag.dk)
APERTURE TABLE:	PERFAG 10A (www.perfag.dk)
BOARD SIZE:	95 x 140 mm
Aprox. Number of holes	420
COMMENTS:	SEE DRILL INFORMATION FILE (A853-PCB-001(2.00).pdf)

COMPONENT SIDE	Dps 5349 090818
TI Denmark A853-PCB-001 (2.00)	



SILKSCREEN COMP	Dps 5349 090818
TI Denmark A853-PCB-001 (2.00)	

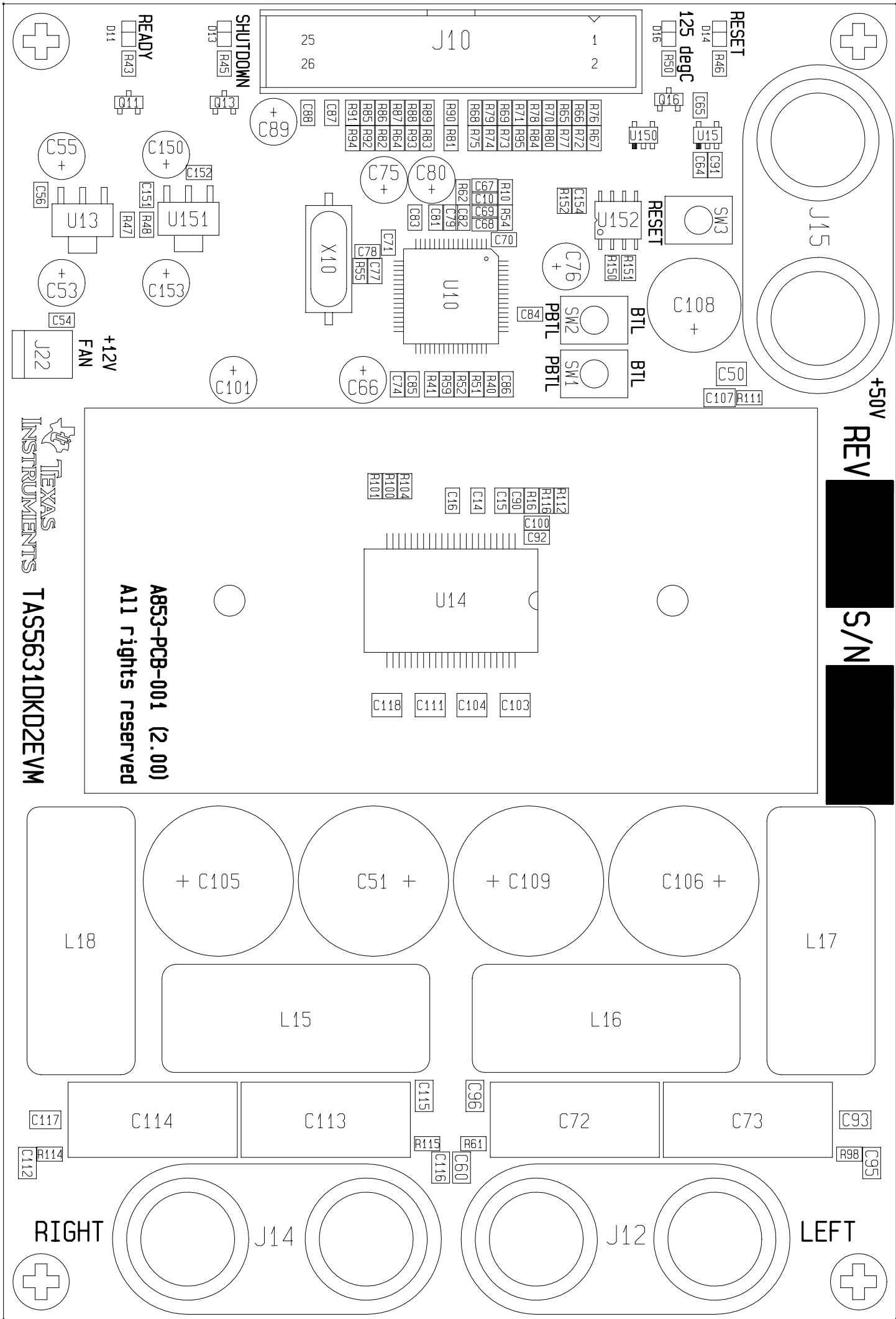



TEXAS INSTRUMENTS
TAS5631DKD2EVM

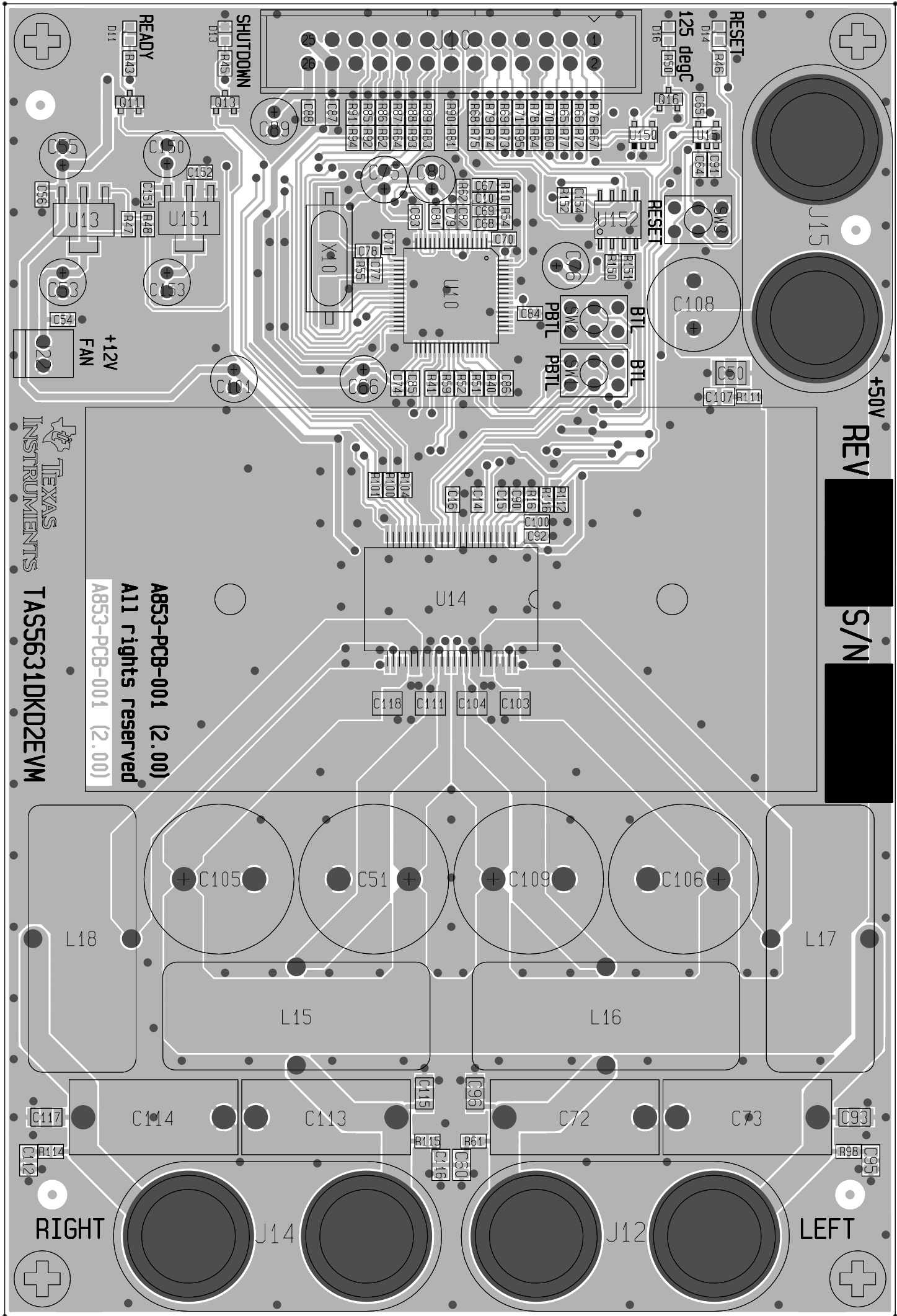
A853-PCB-001 (2.00)
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+50V REV XXXXXXXXXX S/N XXXXXXXXXX

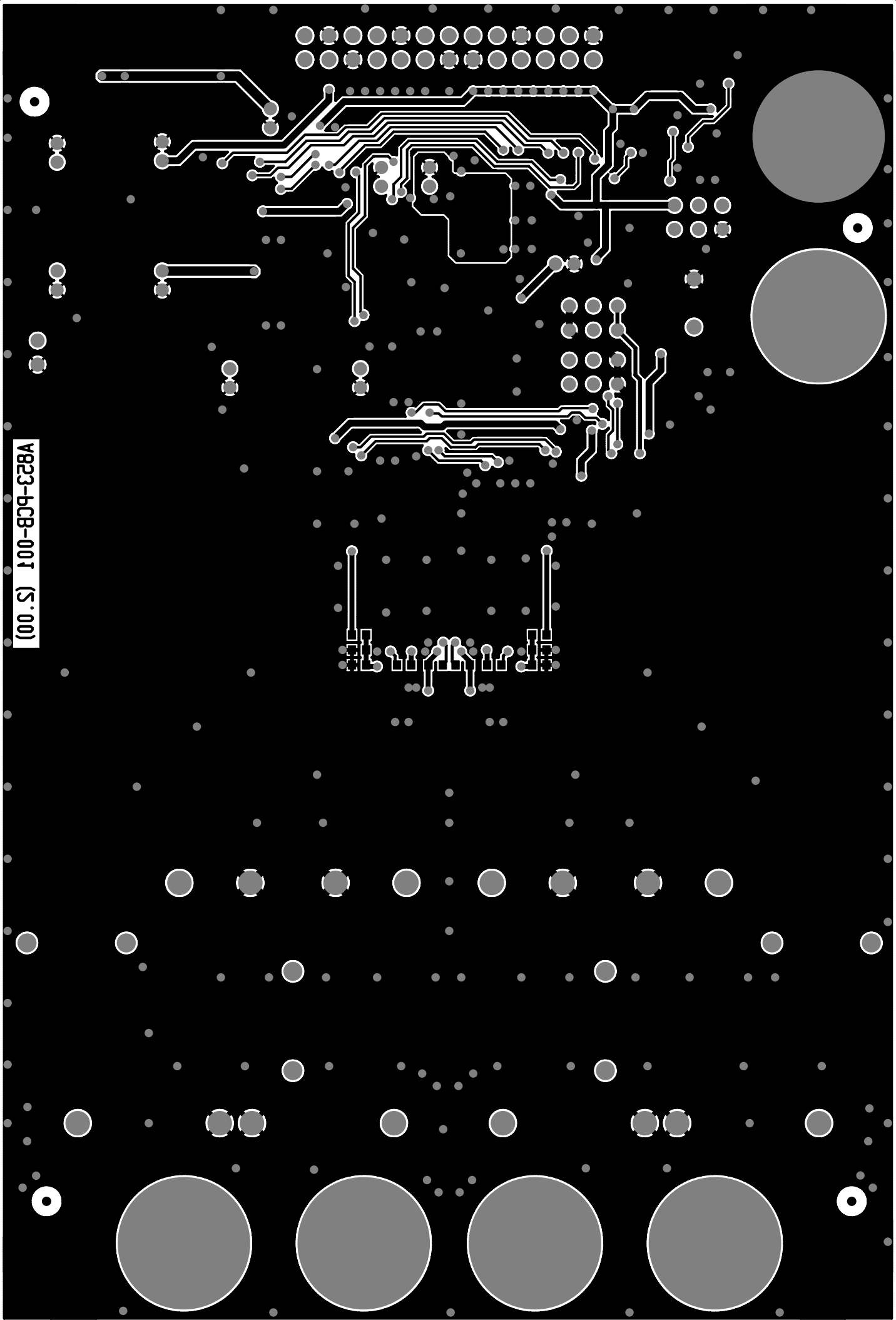
COMP. LAYOUT COMP	DpS 5349 090818
TI Denmark A853-PCB-001 (2.00)	



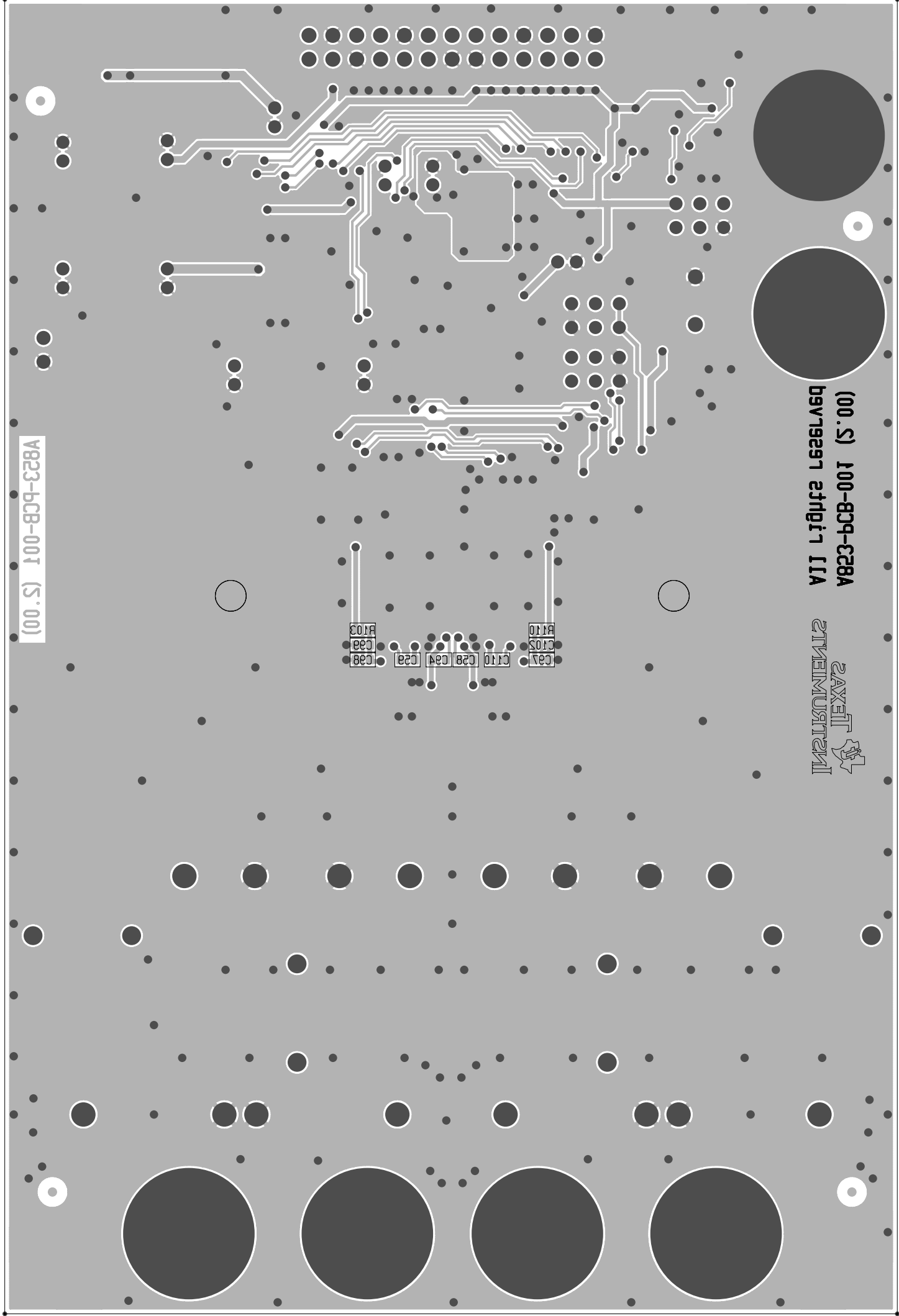
COMPONENT LAYOUTS ICOMP	DpS 5349 090818
TI Denmark A853-PCB-001 (2.00)	



818090 2432 2q0	2012 930J02
TI Dgnmark A823-PCB-001 (S.00)	



TI Dgnmark A823-PCB-001 (S.00)
COMPERLAYOUT 2010 02 23 09 020818

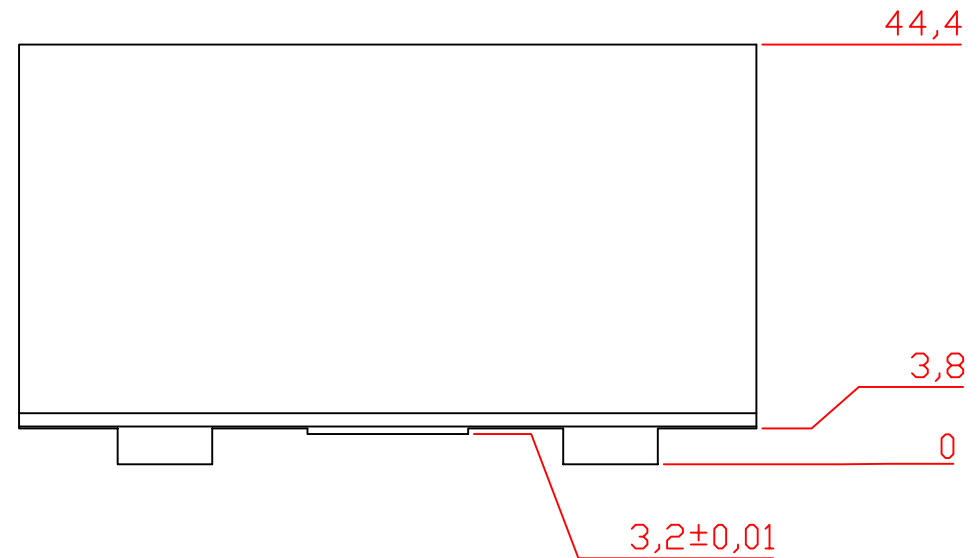
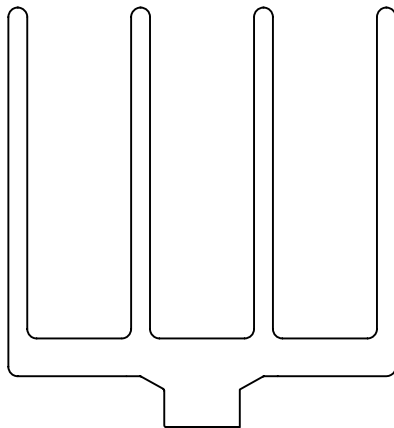
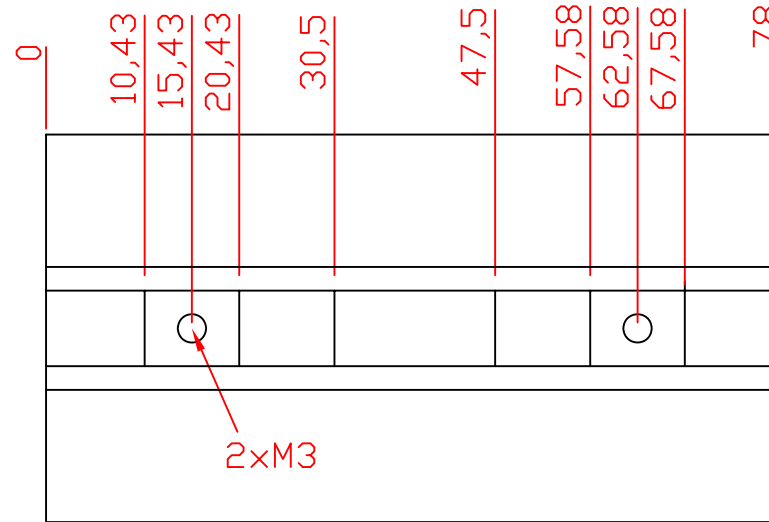


TIC-HSINK-061 (2.00)

Heat sink for 1 DKD44 package

8.July 2008
TIC-HSINK-061 (2.00).dwg

Jonas L. Holm



APPROX. SCALE: 1.25:1

DIMENSIONS: mm

MATERIAL: Profile TIC-HSINK-050(1.00), ALUMINUM

SURFACE: FREE OF SHARP EDGES

SURFACE TREATMENT: BLACK ANODIZED

TOLERANCES: +/- 0.1 mm

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During normal operation, some circuit components may have case temperatures greater than 90°C. The EVM is designed to operate properly with certain components above 125°C as long as the input and output ranges are maintained. These components include but are not limited to linear regulators, switching transistors, pass transistors, and current sense resistors. These types of devices can be identified using the EVM schematic located in the EVM User's Guide. When placing measurement probes near these devices during operation, please be aware that these devices may be very warm to the touch.

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